

ALICE Hardware activities



ALESSANDRO GRELLI

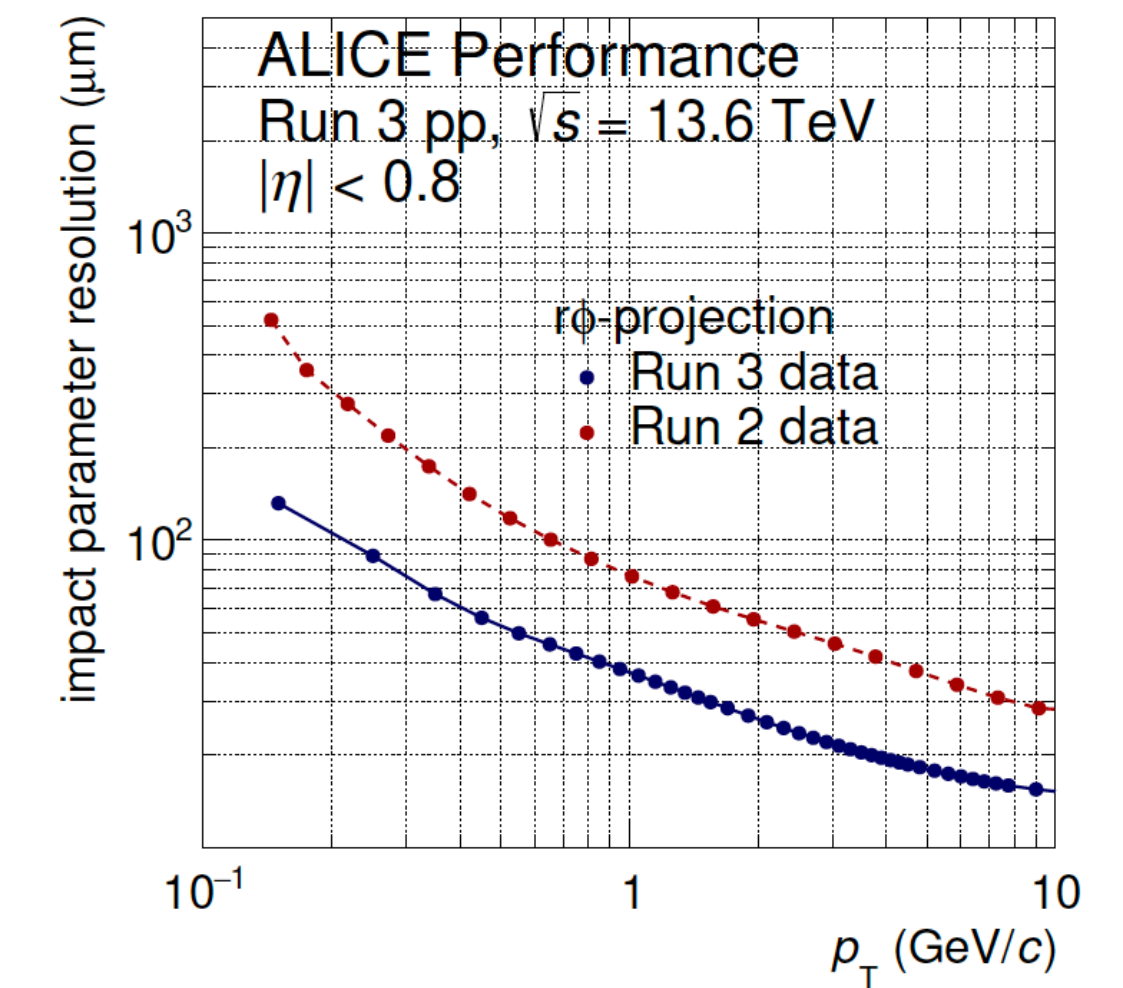
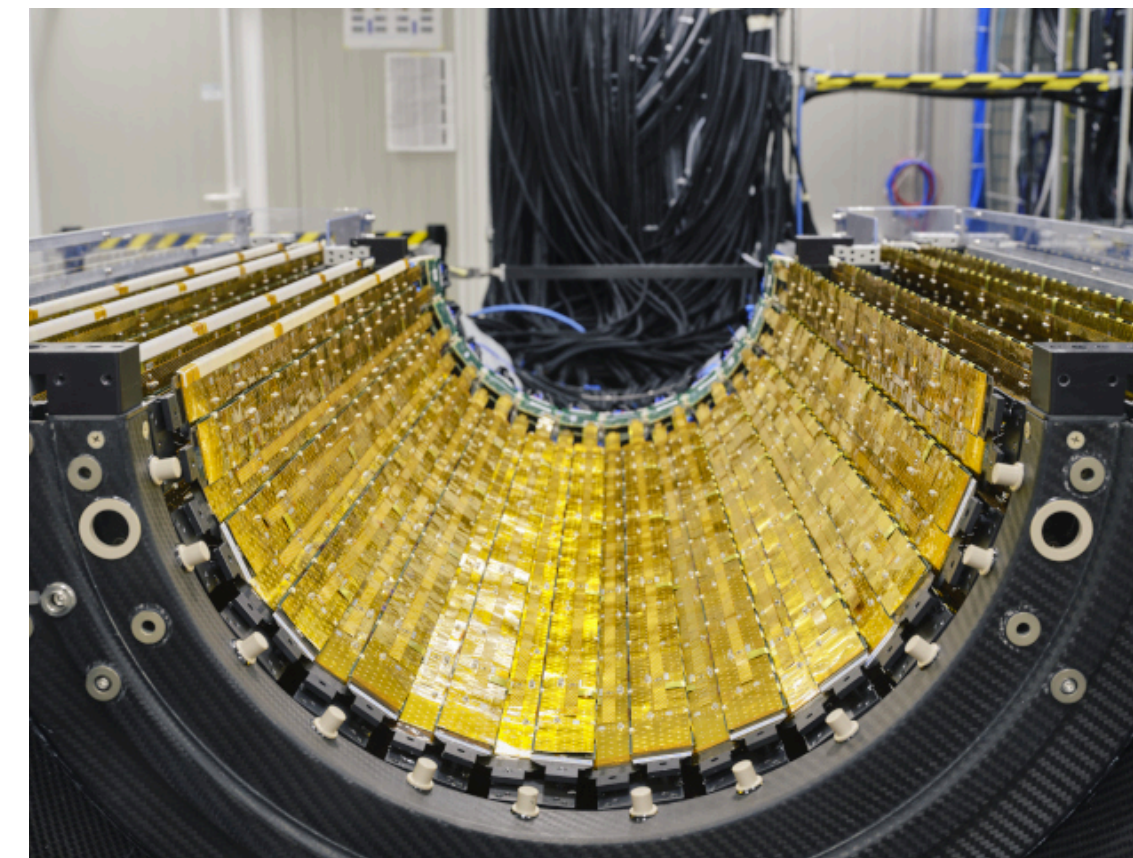
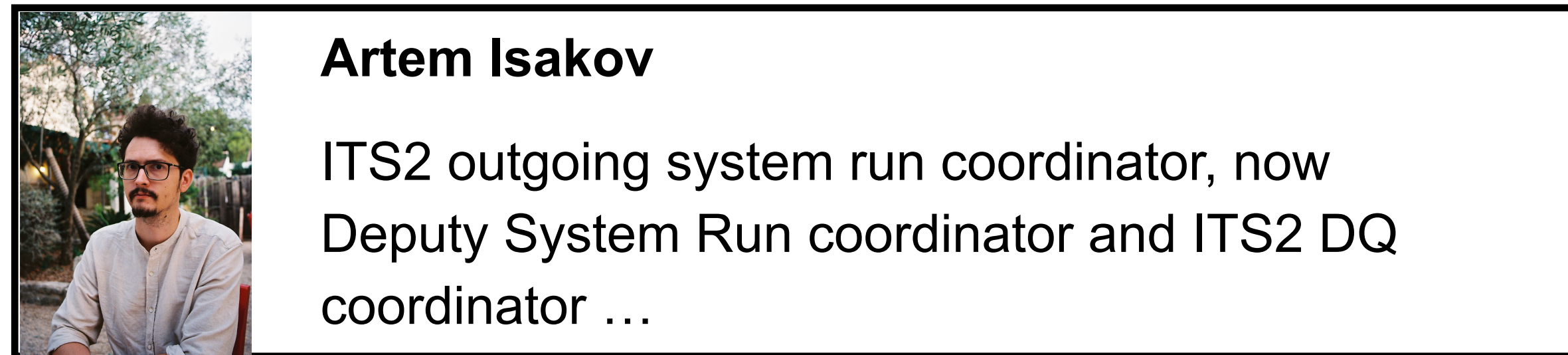
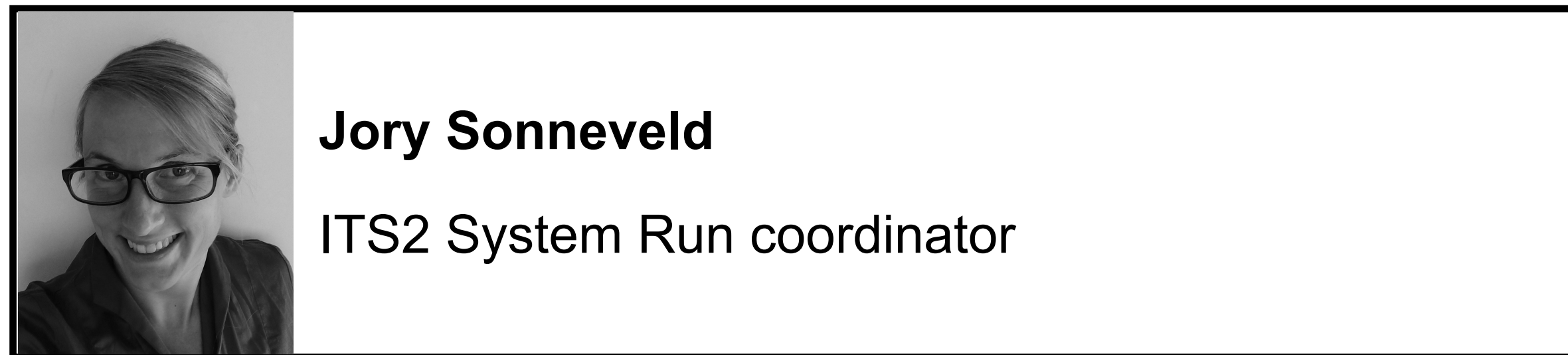
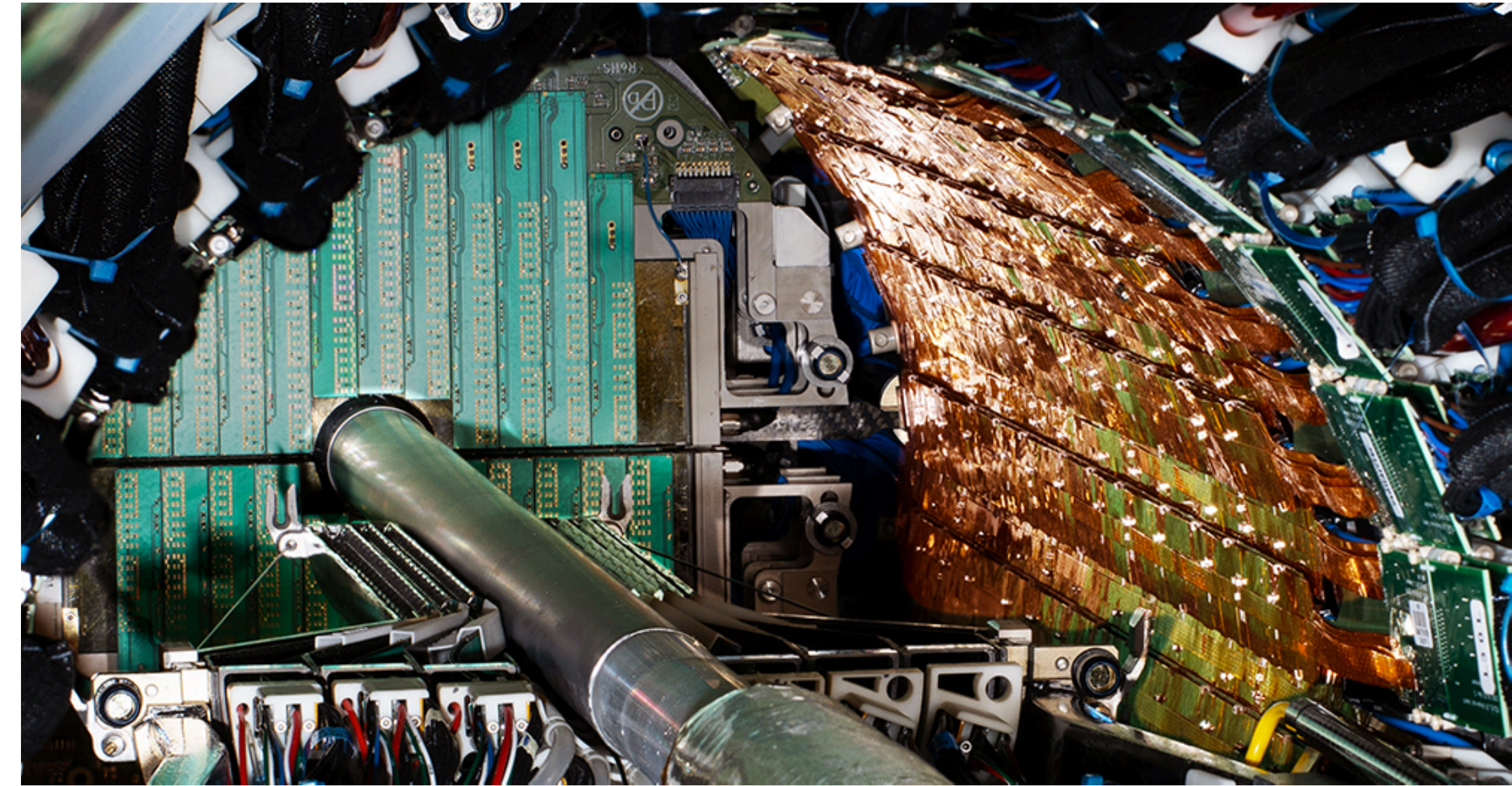


ALICE



Hardware activities: ITS2

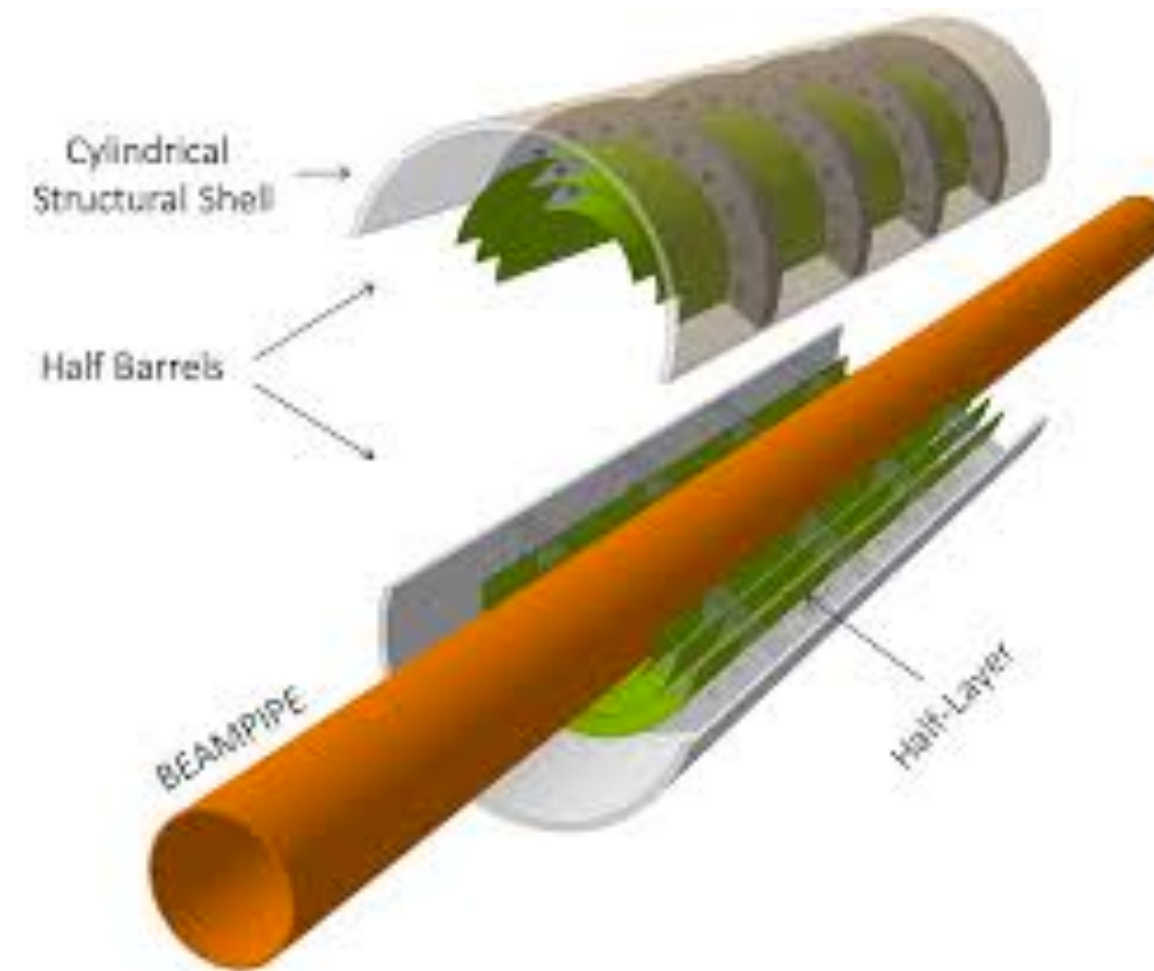
- ✓ New ALICE tracker (ITS2) taking data since 2021-2022. Largest MAPS pixel tracker ever made, $\sim 10 \text{ m}^2$
- ✓ Tracking down to below $p_T \sim 100 \text{ MeV}/c$ with $\sim 40\text{-}70\%$ efficiency and pointing better than $20 \mu\text{m}$ at $1 \text{ GeV}/c$
- ✓ **Large Nikhef involvement** from R&D to assembly and, commissioning, calibration and operation



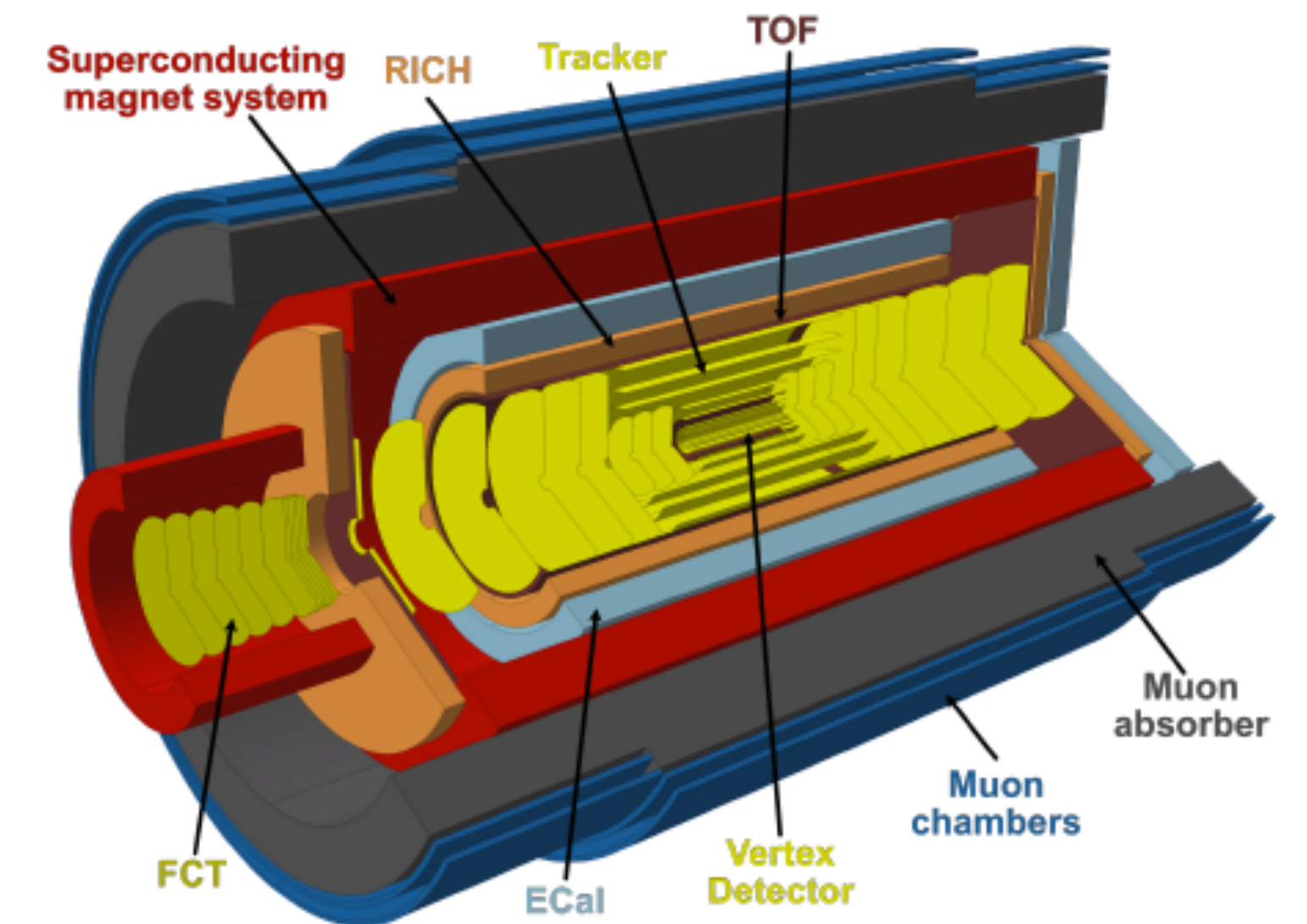
≤ 2022: ITS2



2028: ITS3



2032: ALICE3



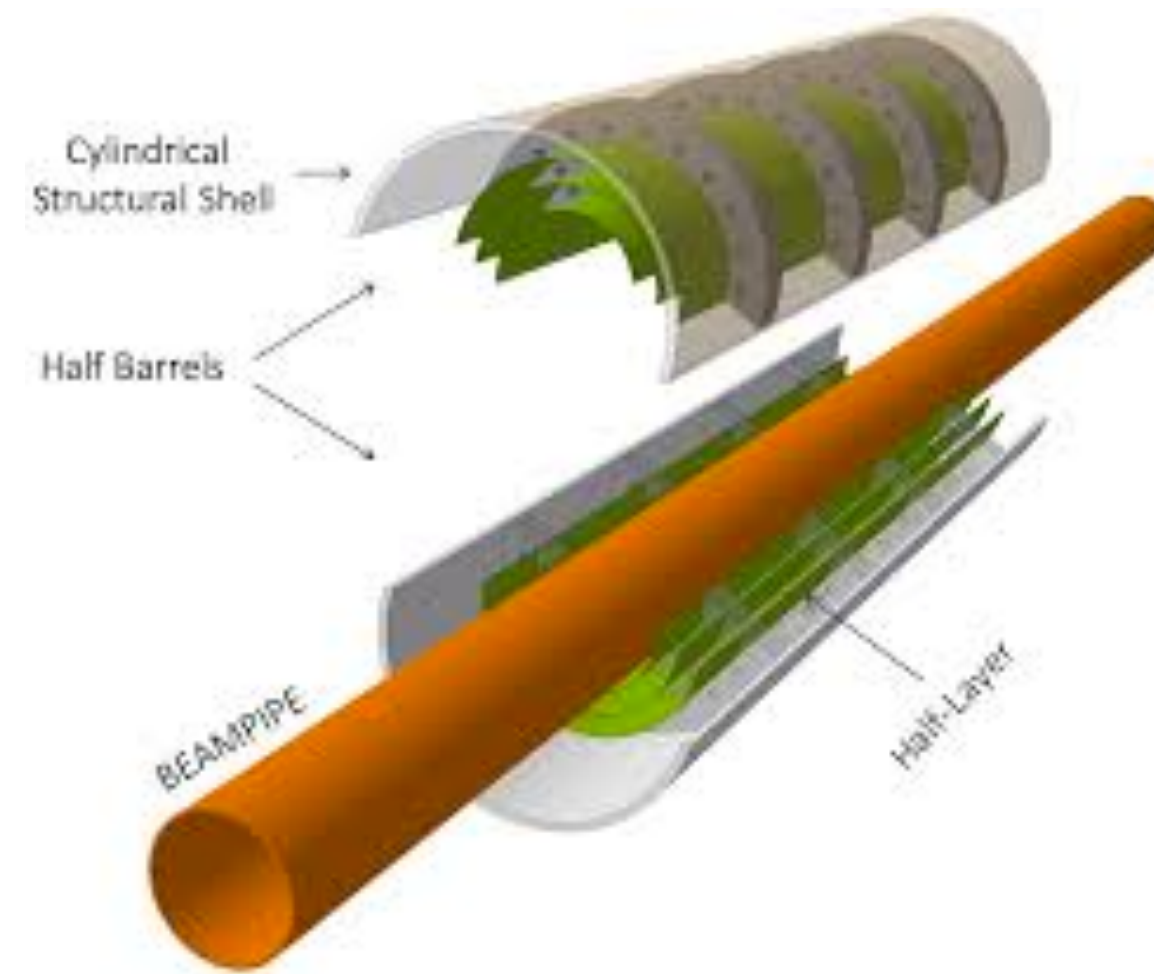
✓ IDEA:

Start sensor design activities on truly cylindrical ultra-light weight sensors (ITS3) with unprecedented spatial resolution targeting 2028. In the mean time profit of this development to start investigating timing technology. After 2028 the goal is to conjugate ps time resolution, low power and mum spatial resolution (ALICE3)

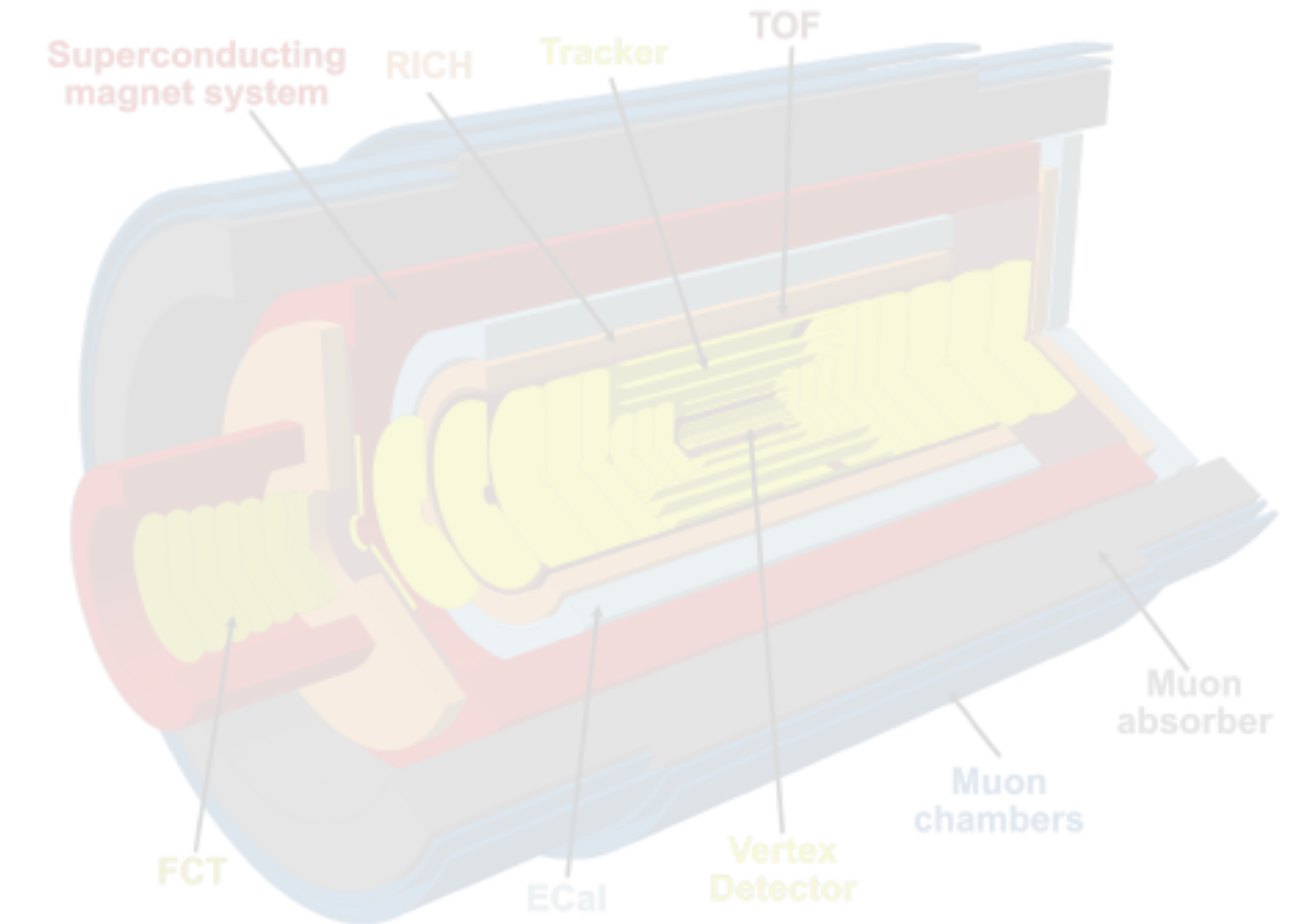
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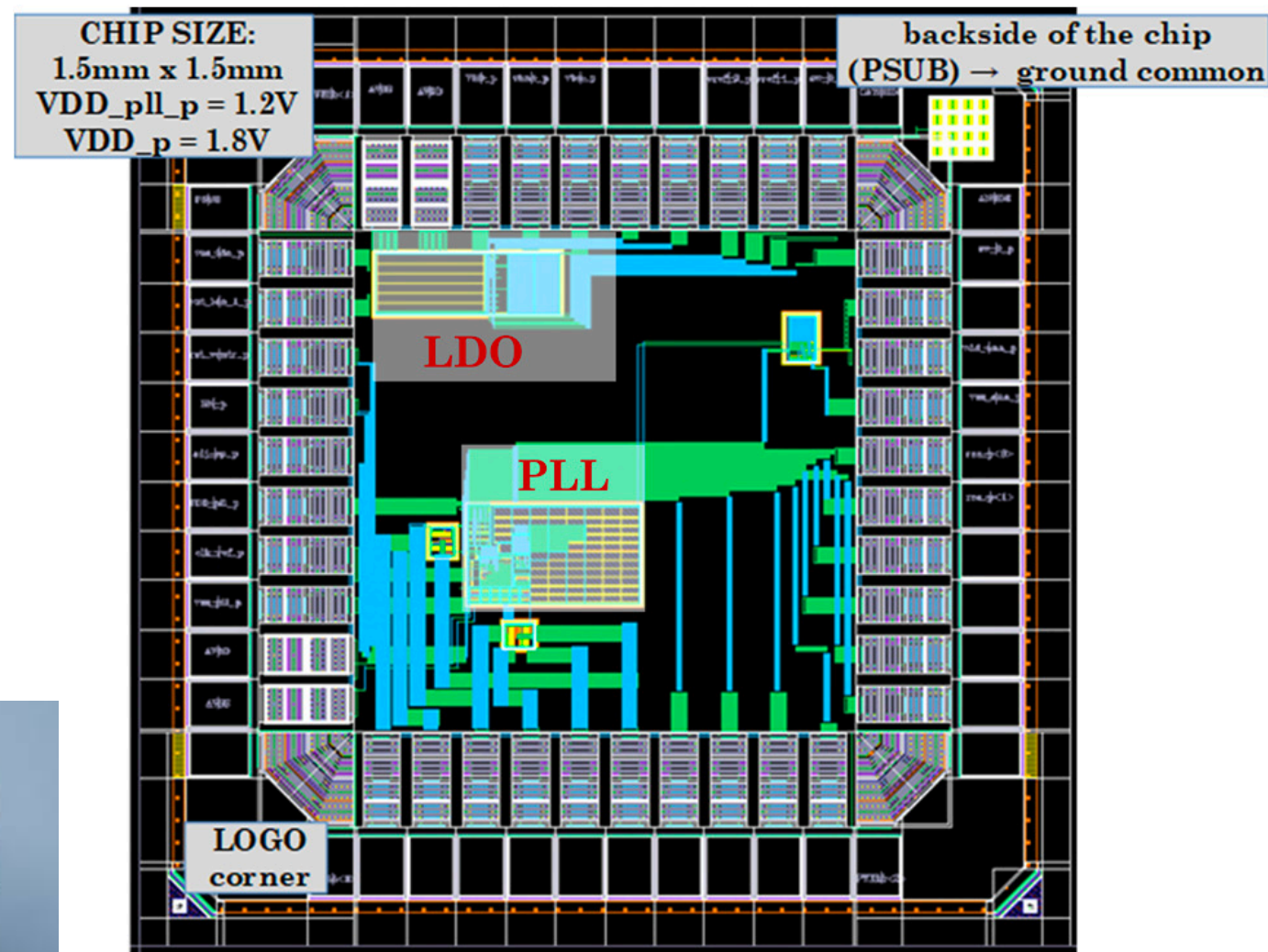


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ALICE ITS3 @Nikhef

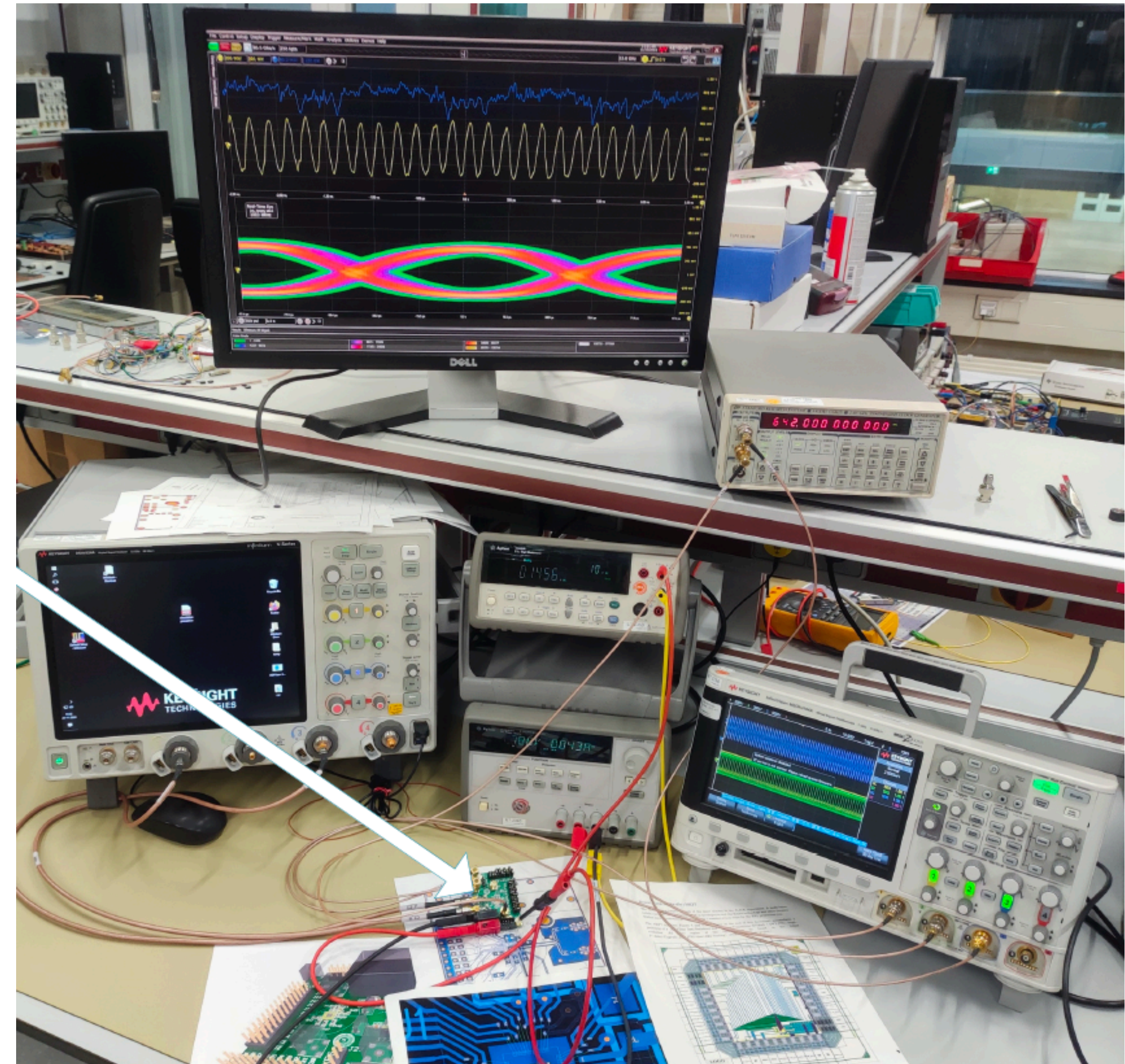
- ✓ Nikhef is designing the **ITS3 serialiser at 10.24 Gb/s** and later
The ITS3 fast link will be validated in Utrecht/Nikhef
- ✓ Serialiser analog core as well as PLL and LDO already available
as test chips. Characterisation in house and at radiation
facilities ongoing



Vladimir

Arsenij

Djan



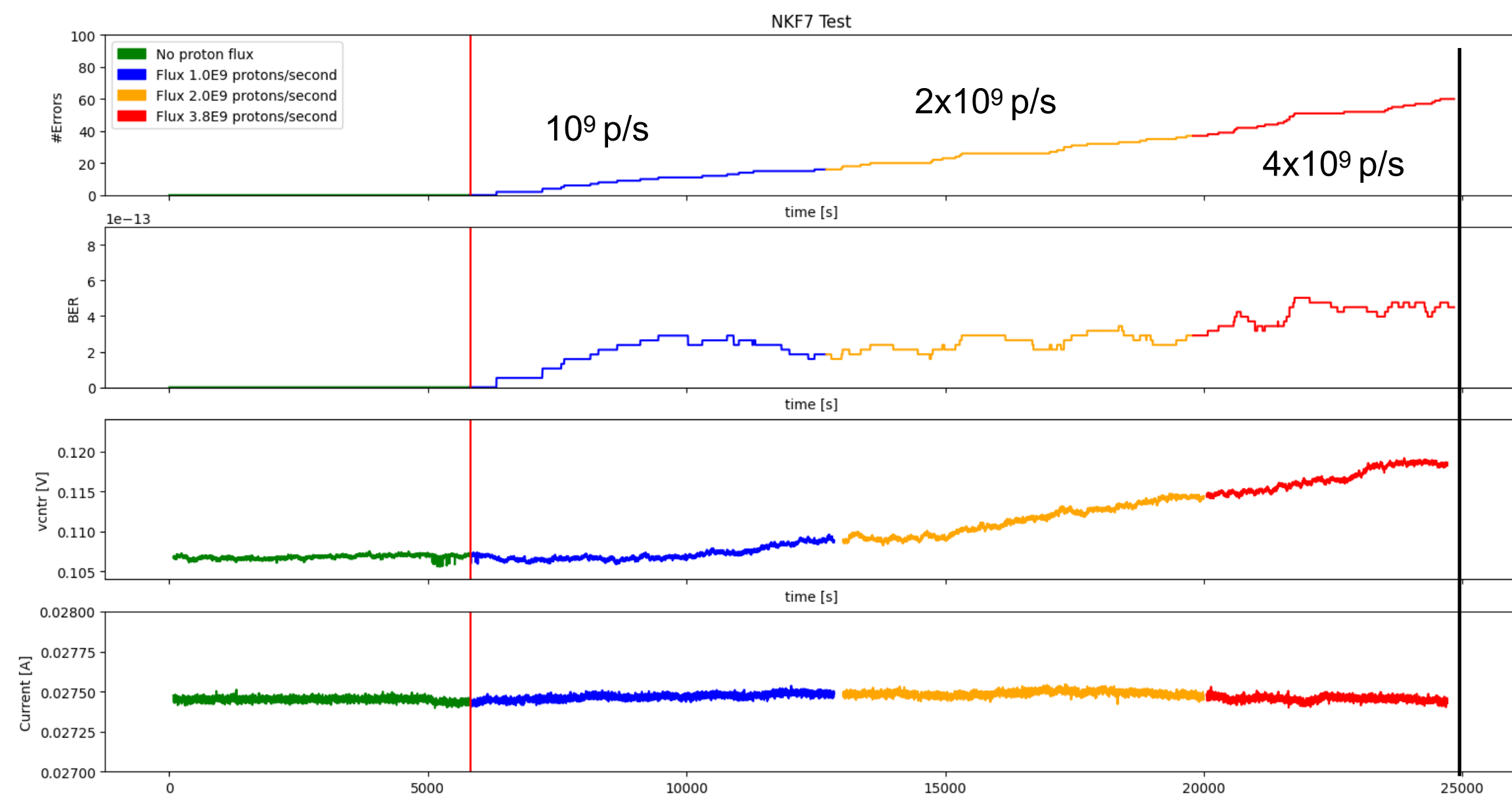
Super thanks to our ET group and especially to Ruud, Vladimir, Arsenij and Omar!!!

ALICE ITS3 @Nikhef

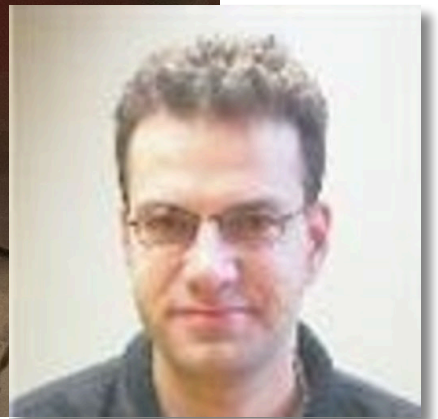
- ✓ Nikhef designed test structures tested for radiation last week in Prague cyclotron facility.
- ✓ Test beam has been successful, data are being analysed as we speak

Beam on

16 Mrad dose



Single event upset cross-section $\sim 10^{-12}$

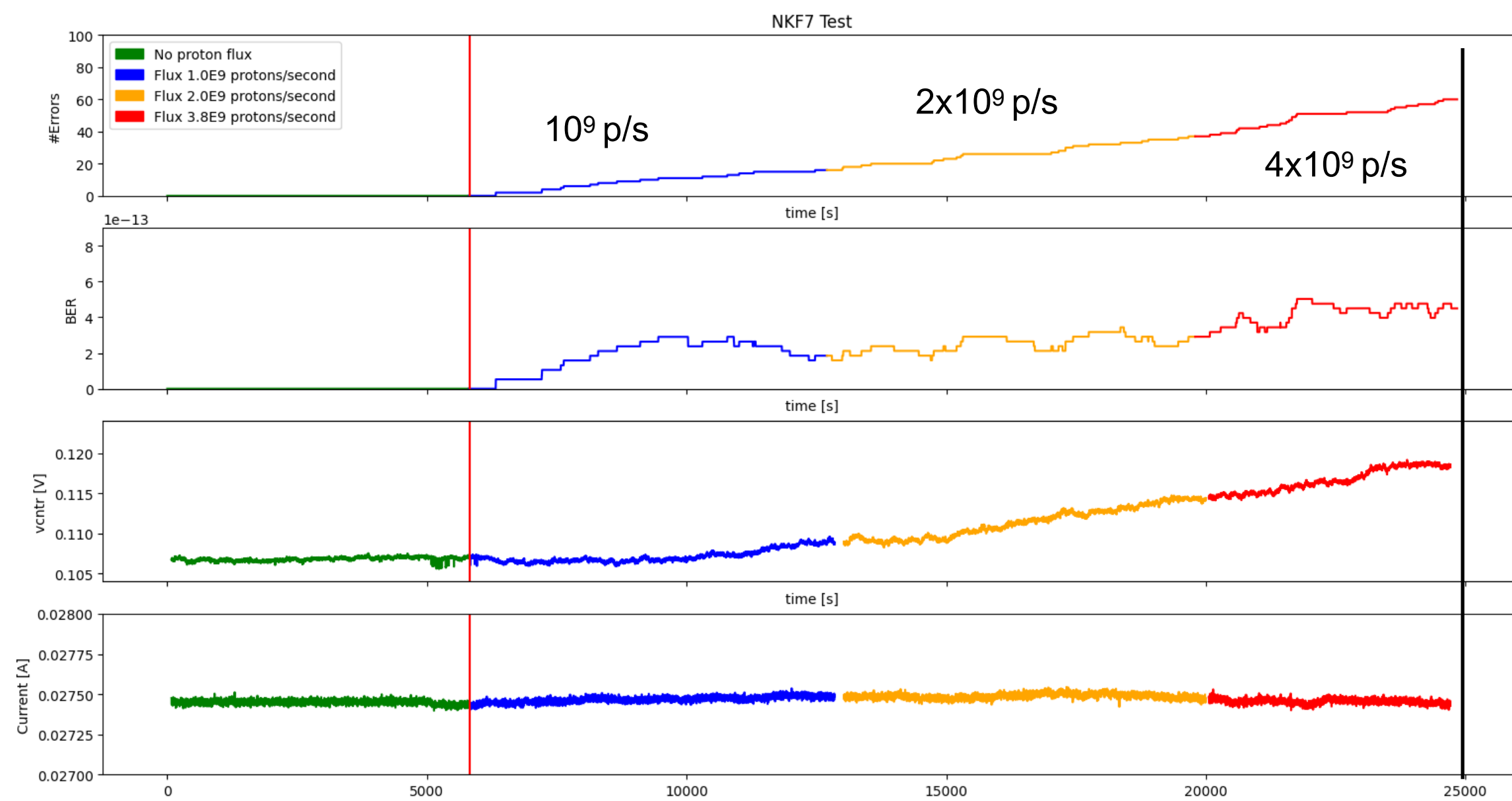


ALICE ITS3 @Nikhef

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Beam on

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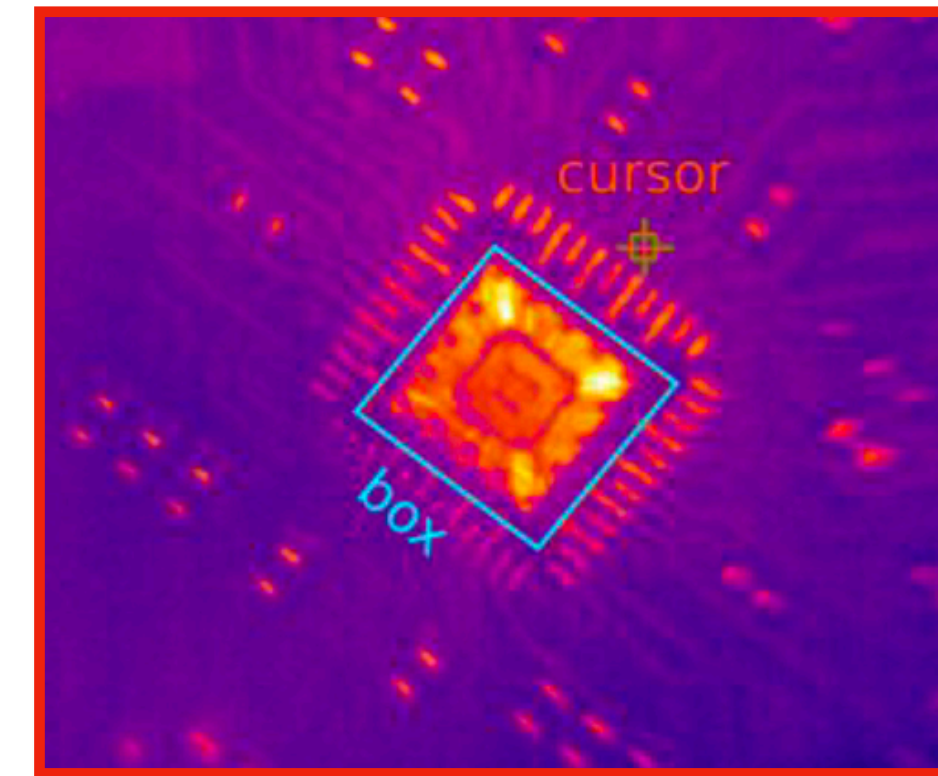
Single event upset cross-section ~ 10⁻¹²



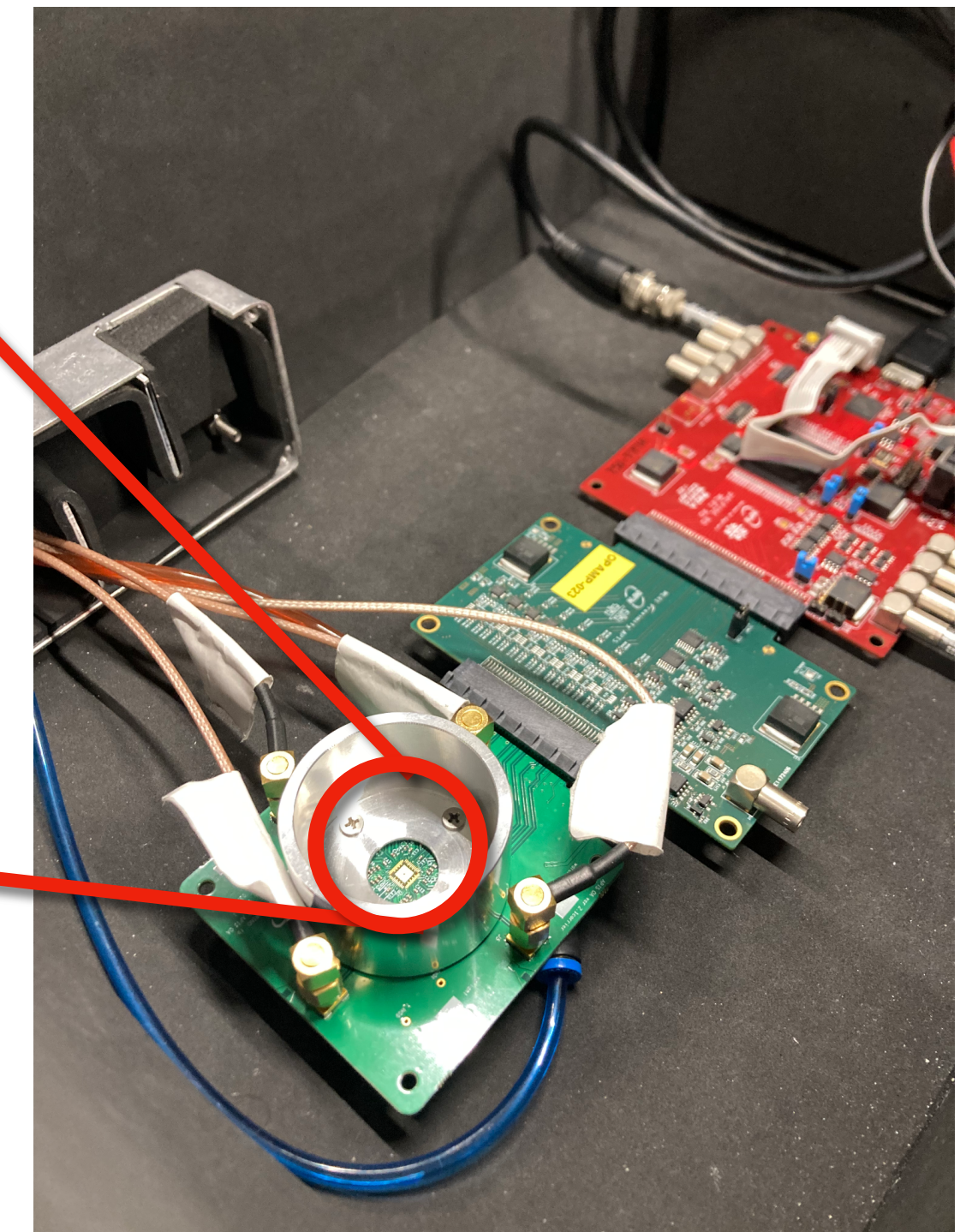
MAPS radiation hardness: APTS

- ☑ Analog test structure (APTS) at testy beam proved to survive 10^{15} neutron equivalent flux. **Can we go higher? Can we prove that maps are still operational at 10^{16} ?**
- ☑ At present we have APTS chips irradiated up to 10^{16} . We prepared a setup to measure **leakage currents** and verify their operational status

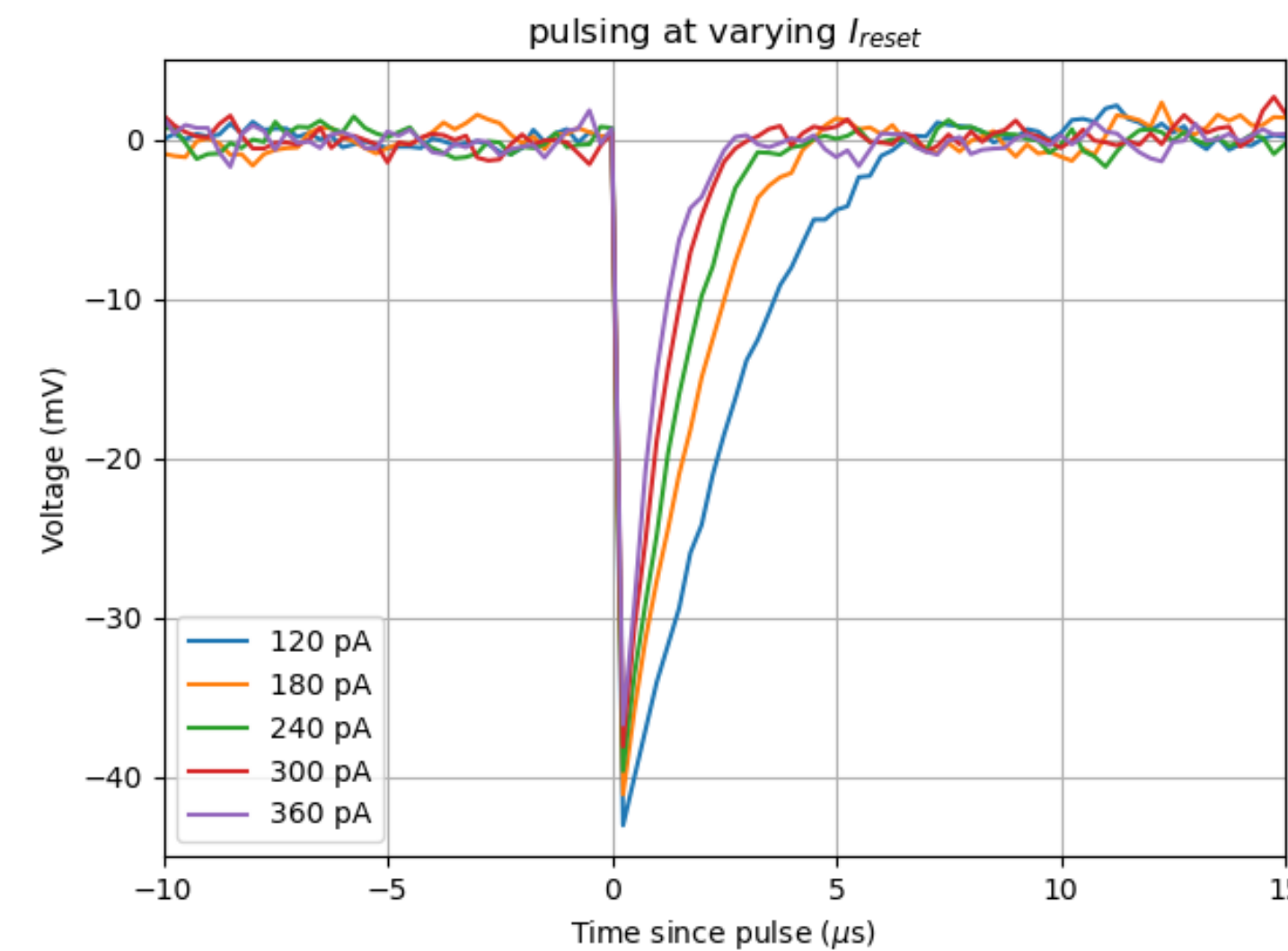
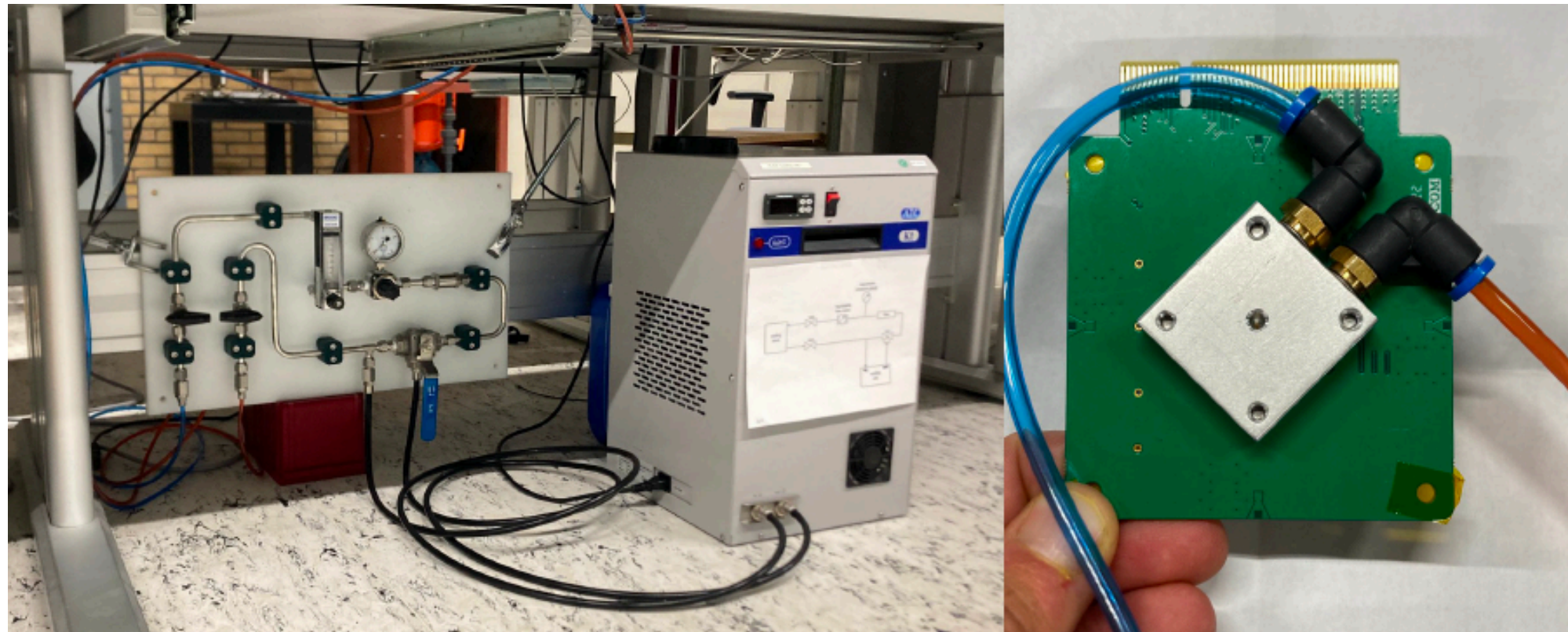
APTS chip under thermal camera



Charge calibration



Cooling test nikhef setup



Isis

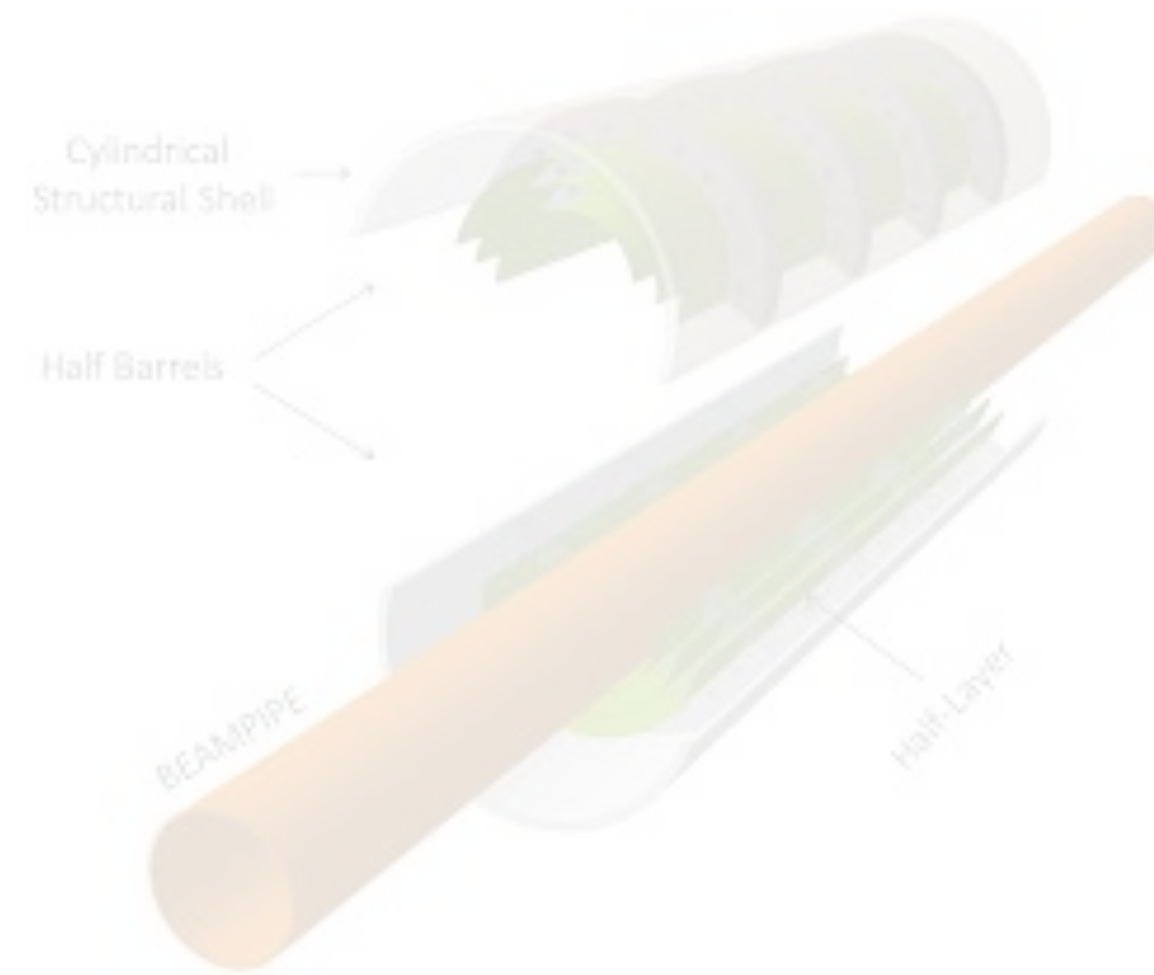


Work ongoing! Stay tuned

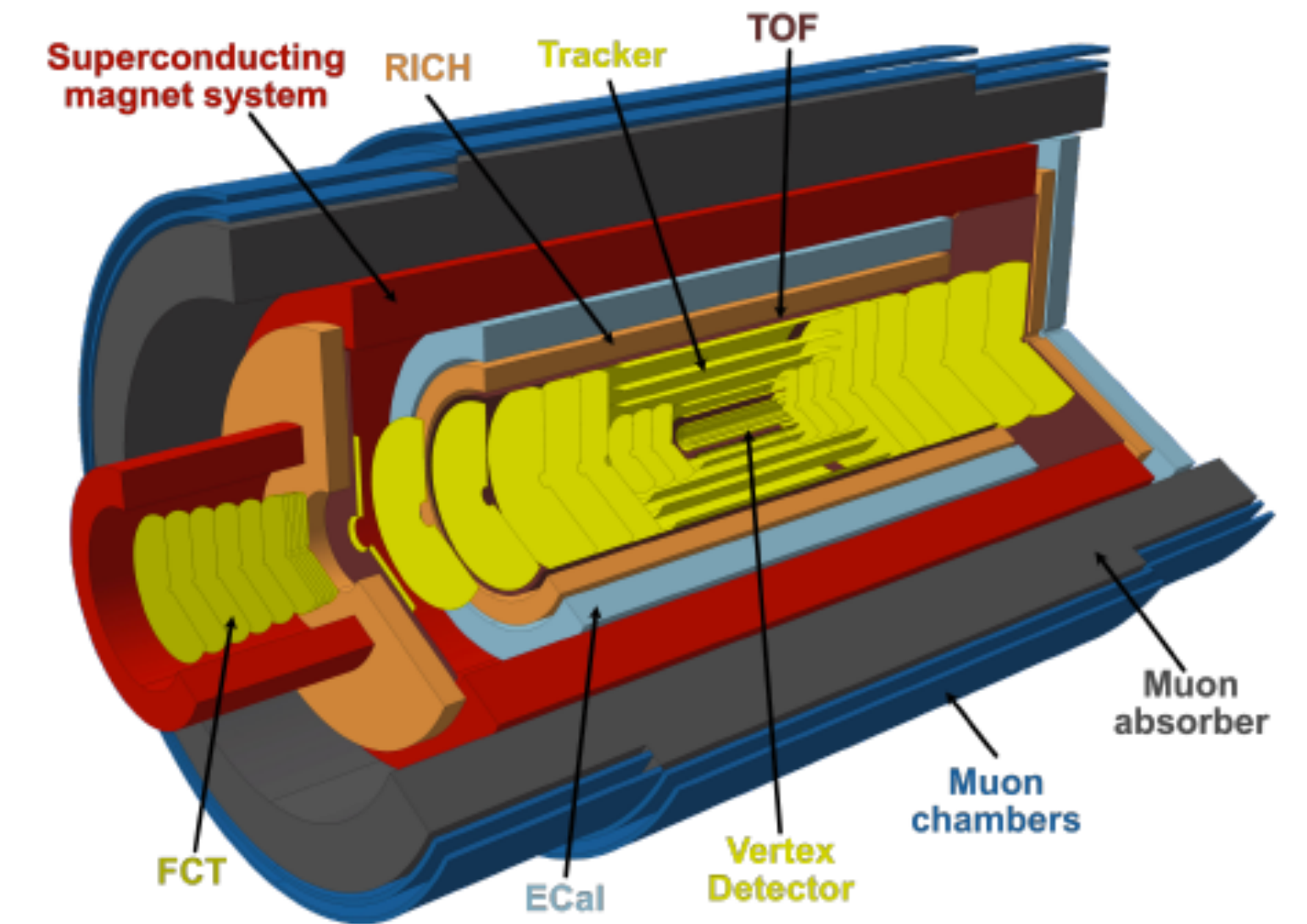
≤ 2022: ITS2



2028: ITS3



2032: ALICE3



✓ IDEA:

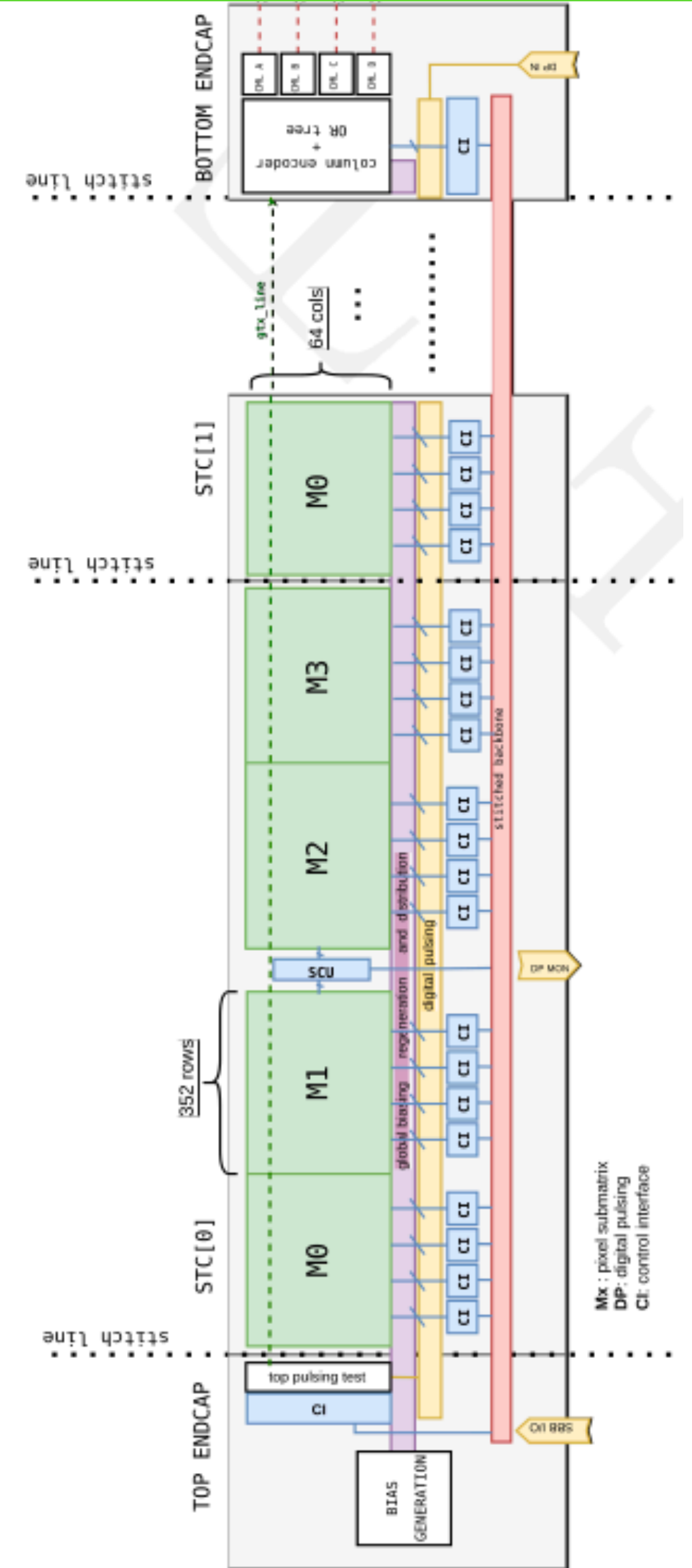
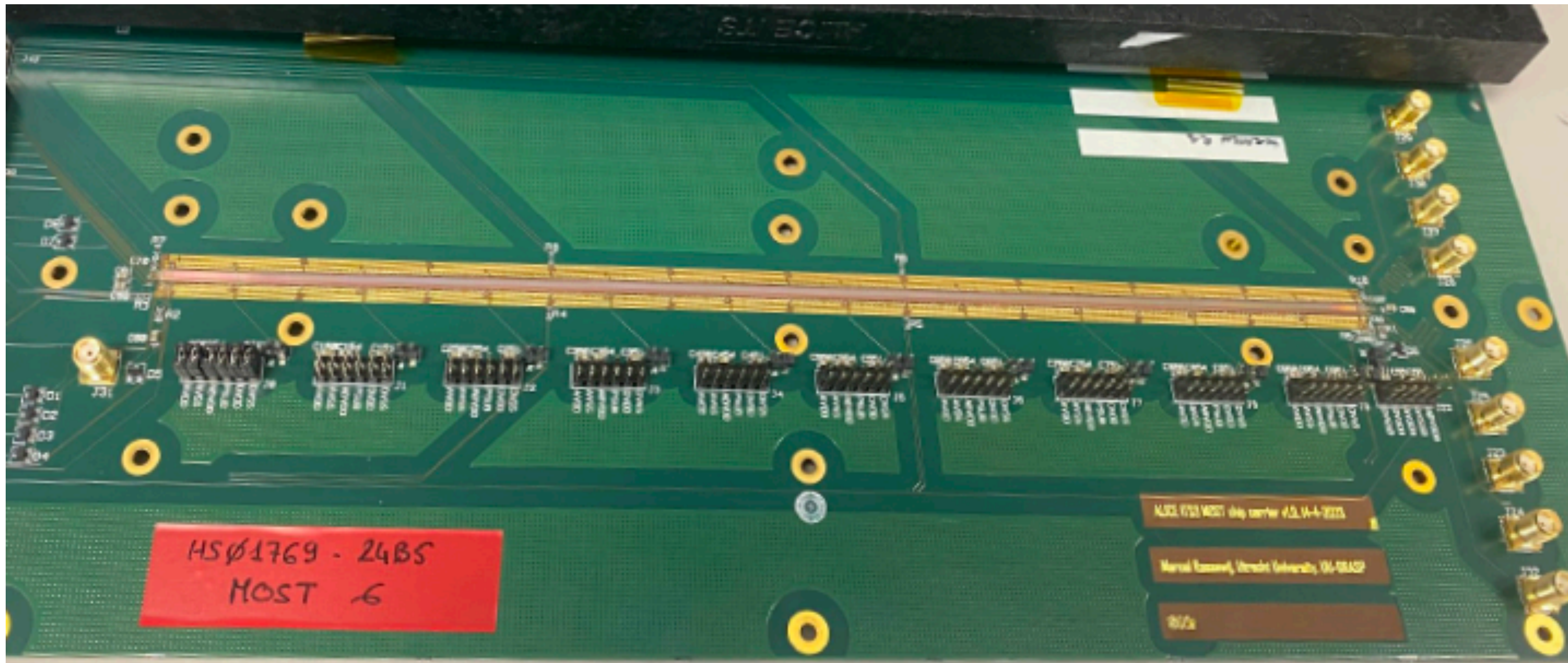
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A selection of activities: MOST

Design: (Nikhef) Arsenij Vitkovsky and CERN



- ✓ **MOST**: **MO**nolithic **S**titched sensor with **T**iming
- ✓ First stitched sensor (25cm x 2 mm) with timing capabilities

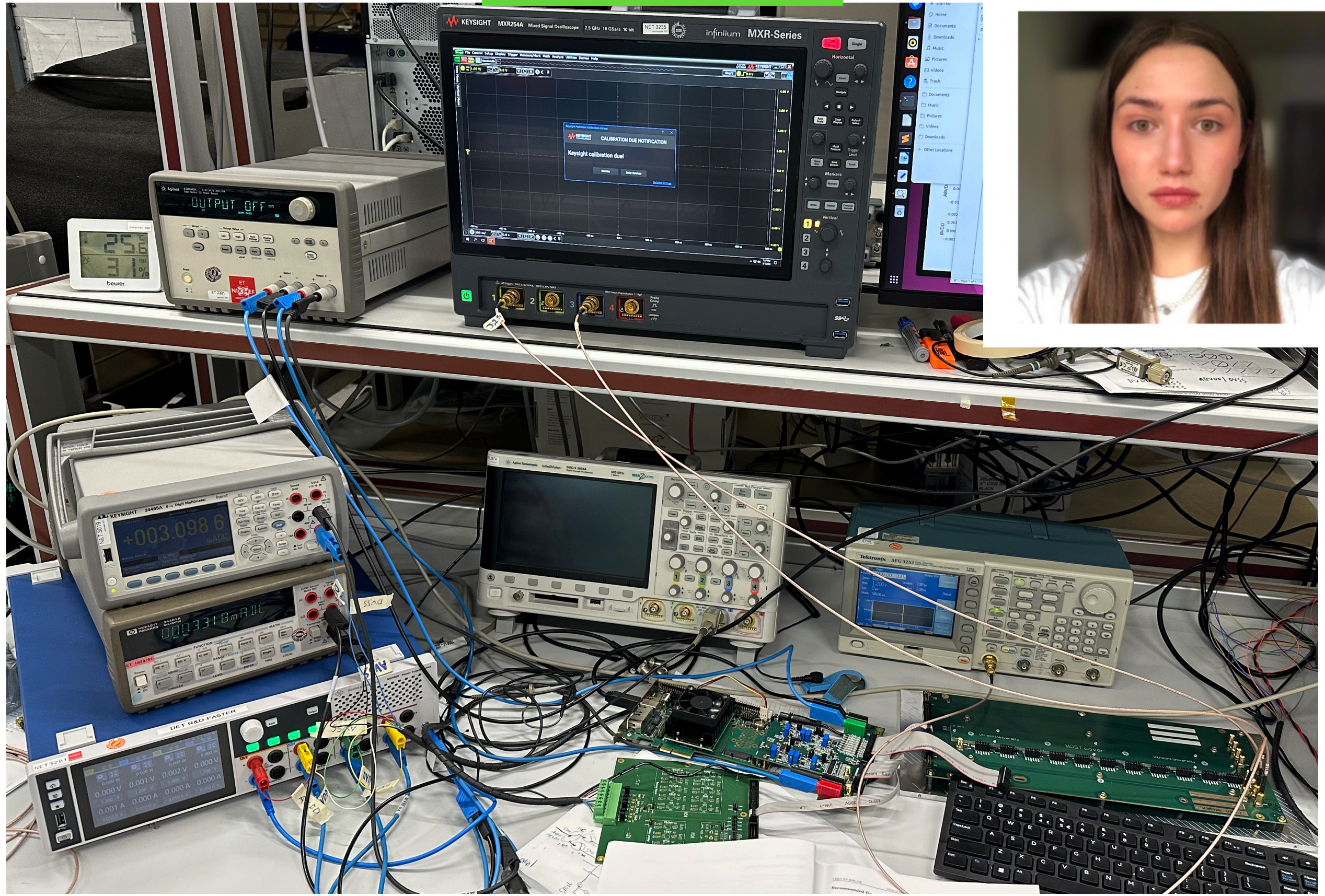


A selection of activities: MOST

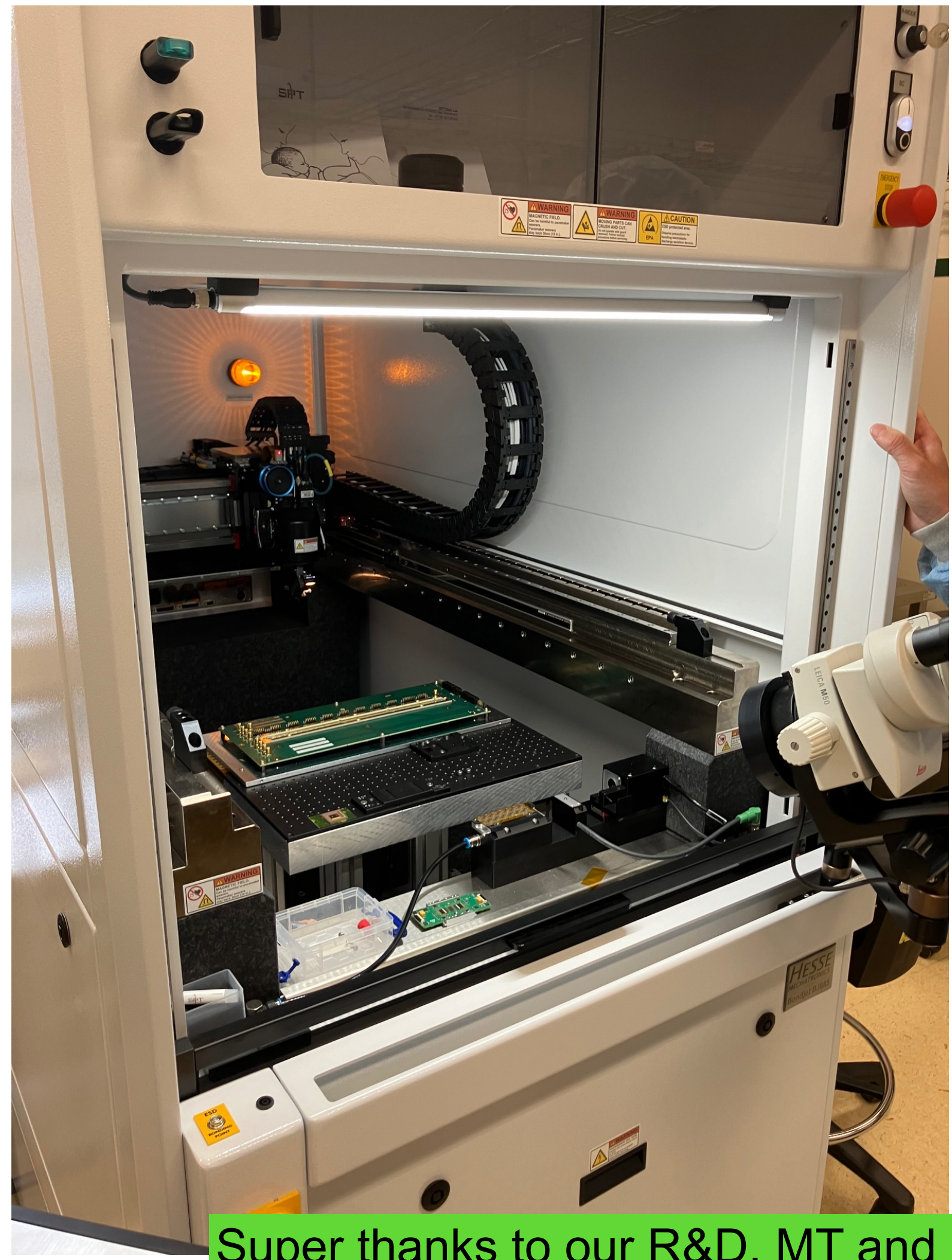
☑ MOST Characterisation

Test setup at R&D

Mariia



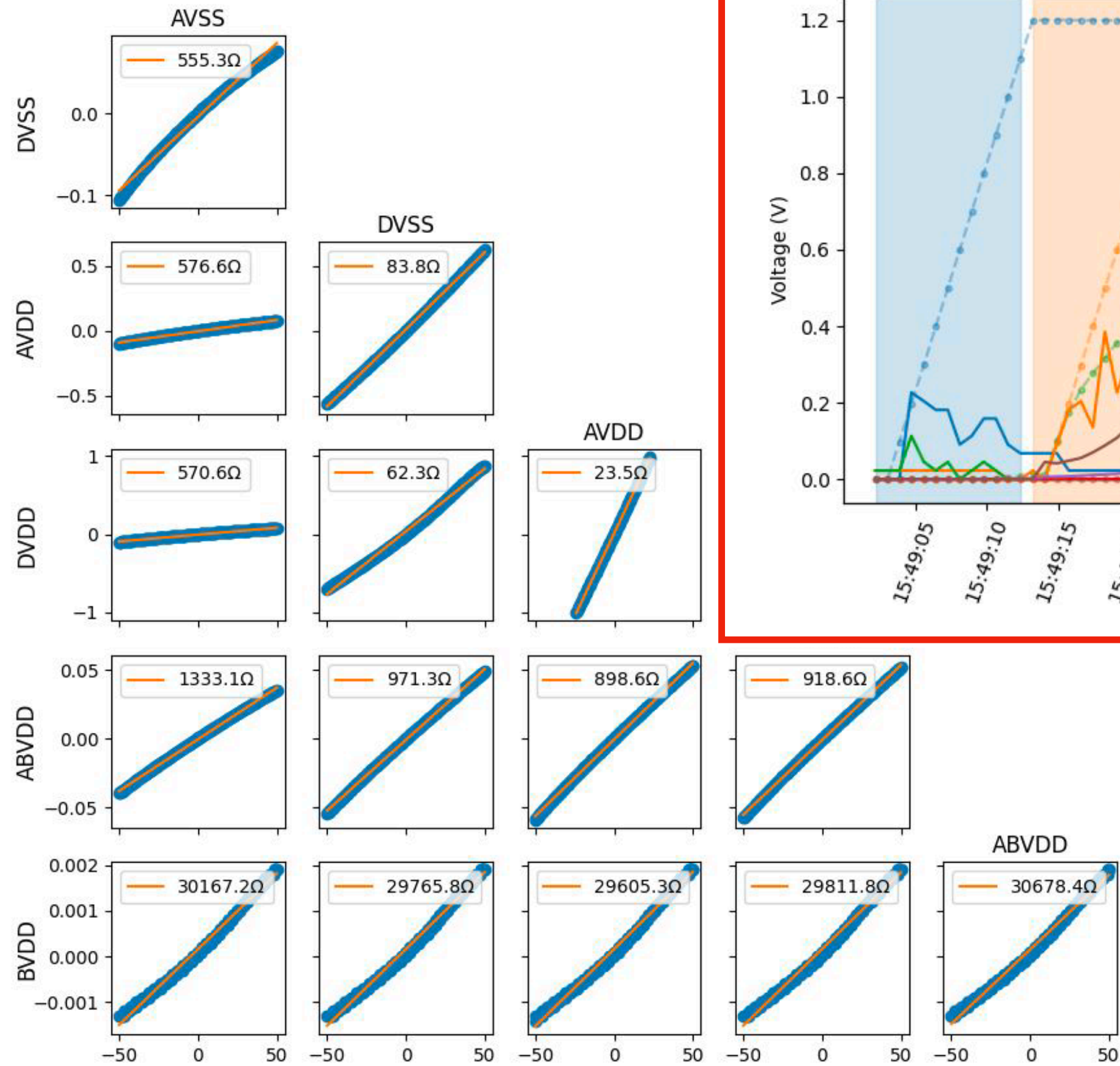
Bonding tests



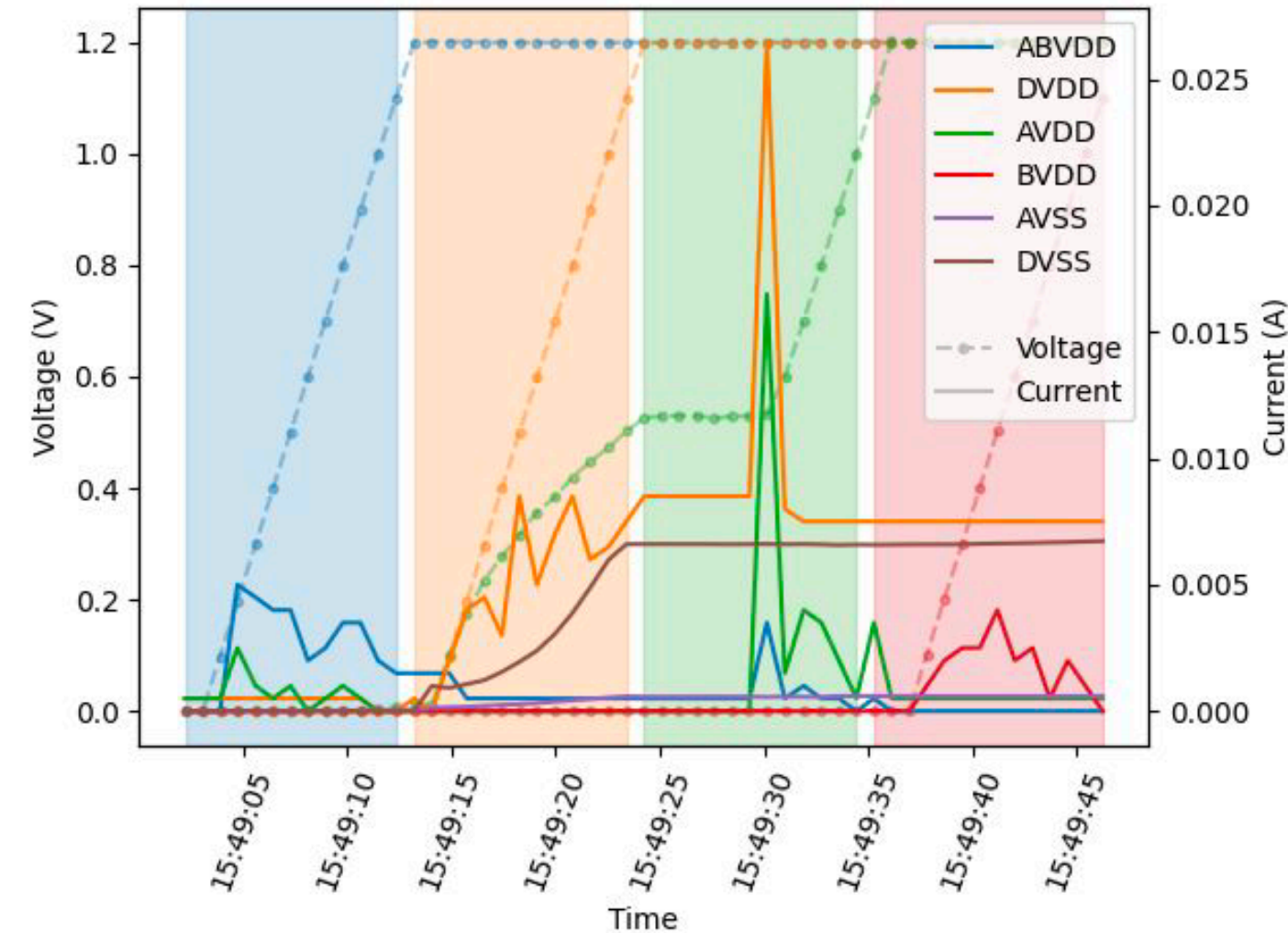
Super thanks to our R&D, MT and ET group!!!

A selection of activities: MOST

Impedance tests



Powering up tests

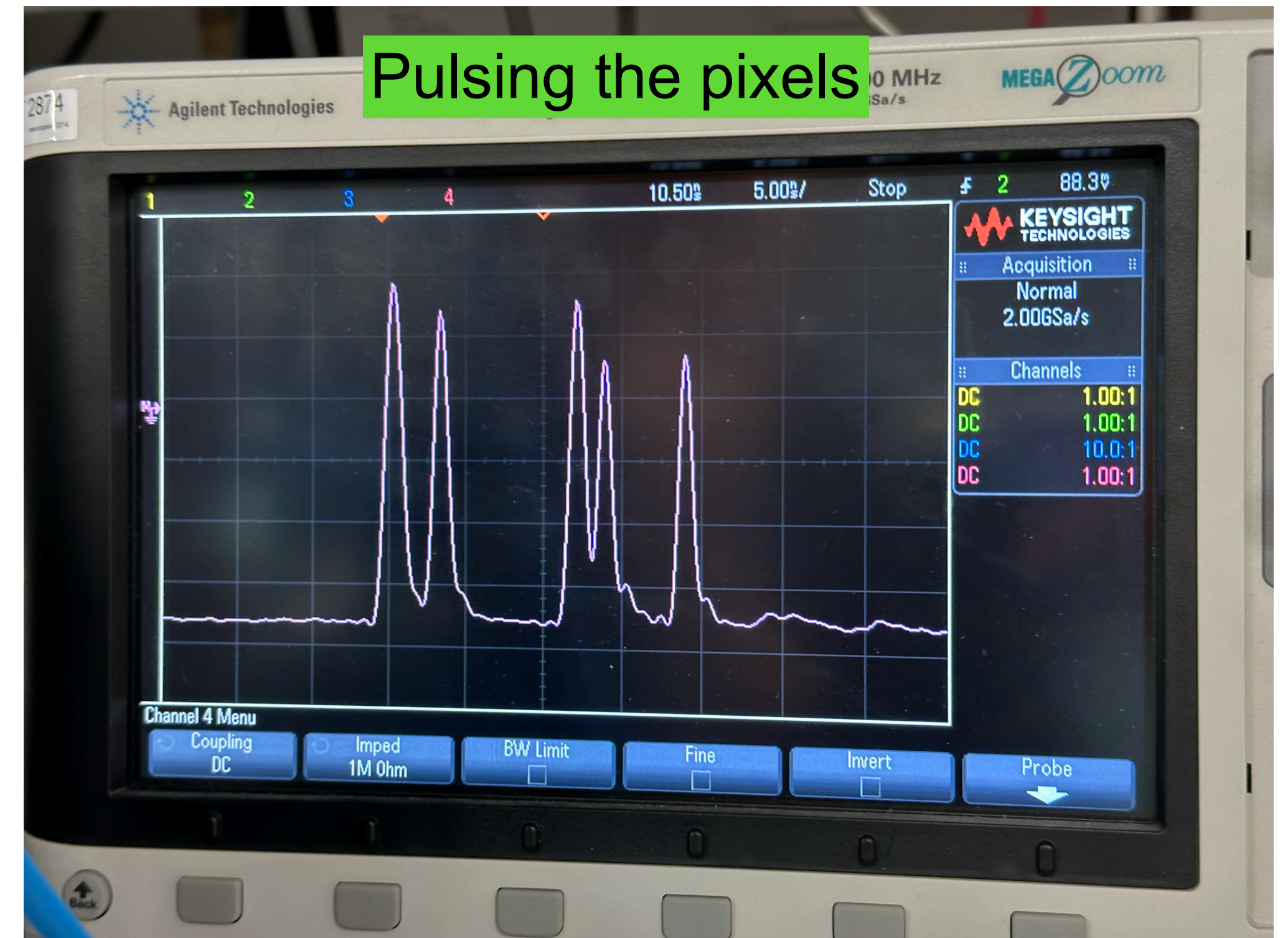


☑ Nilkhef work on MOST

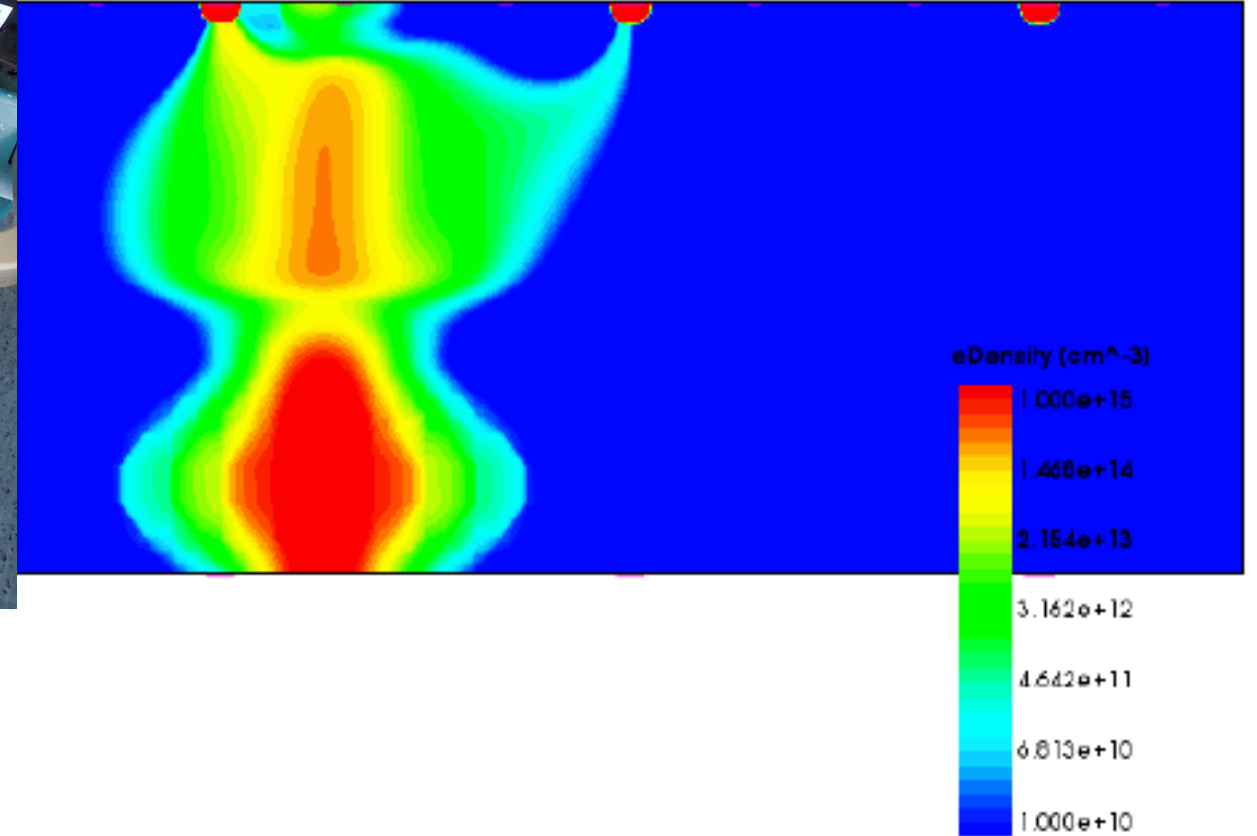
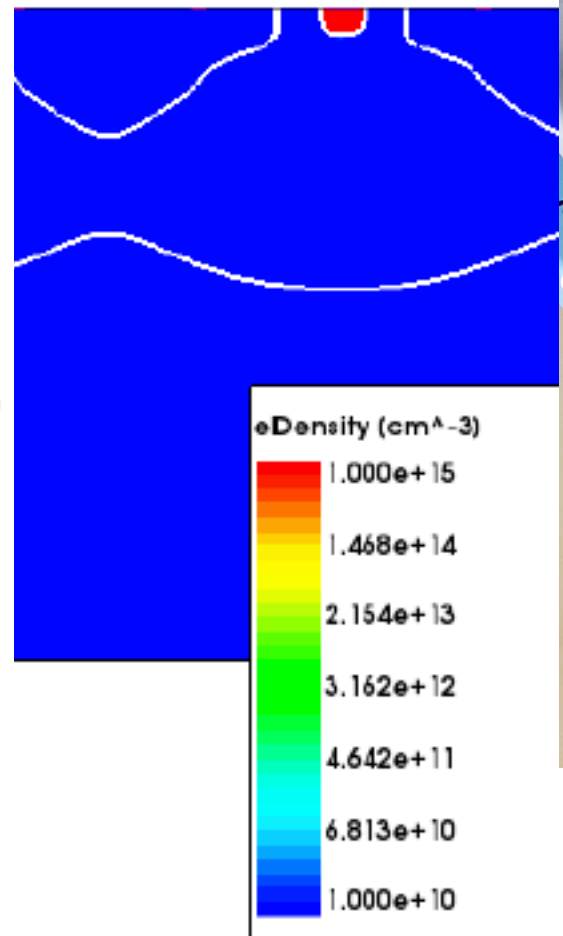
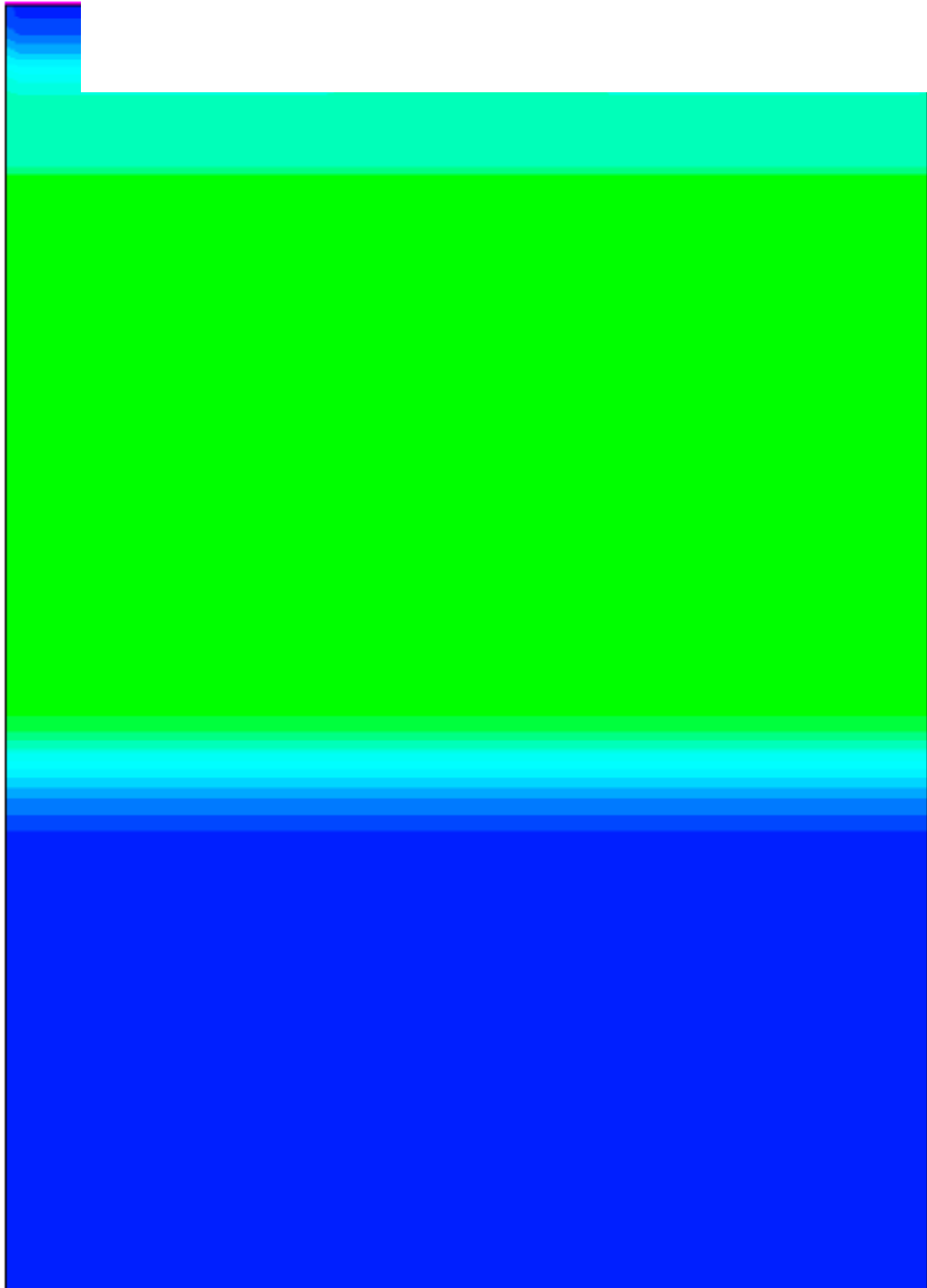
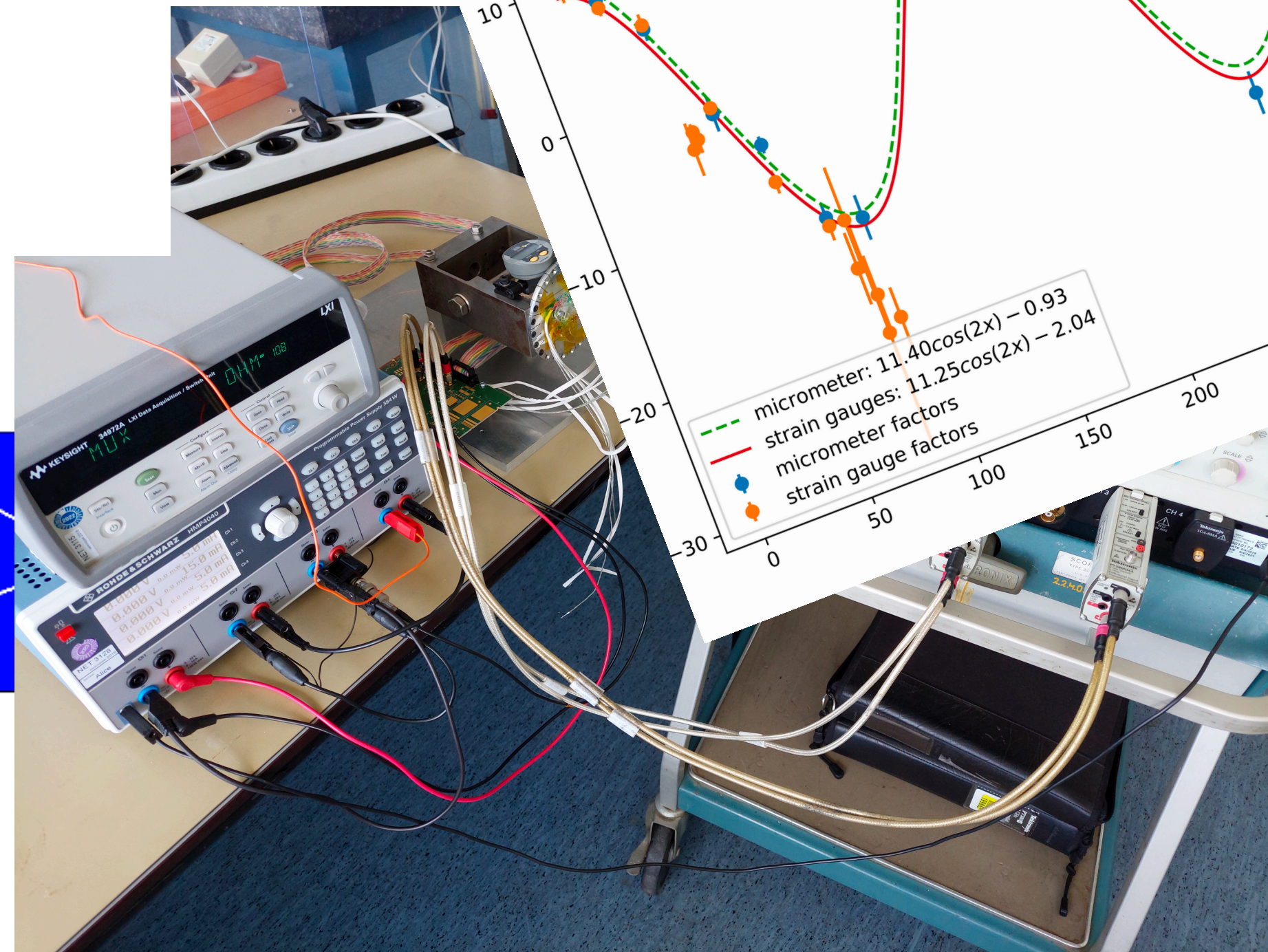
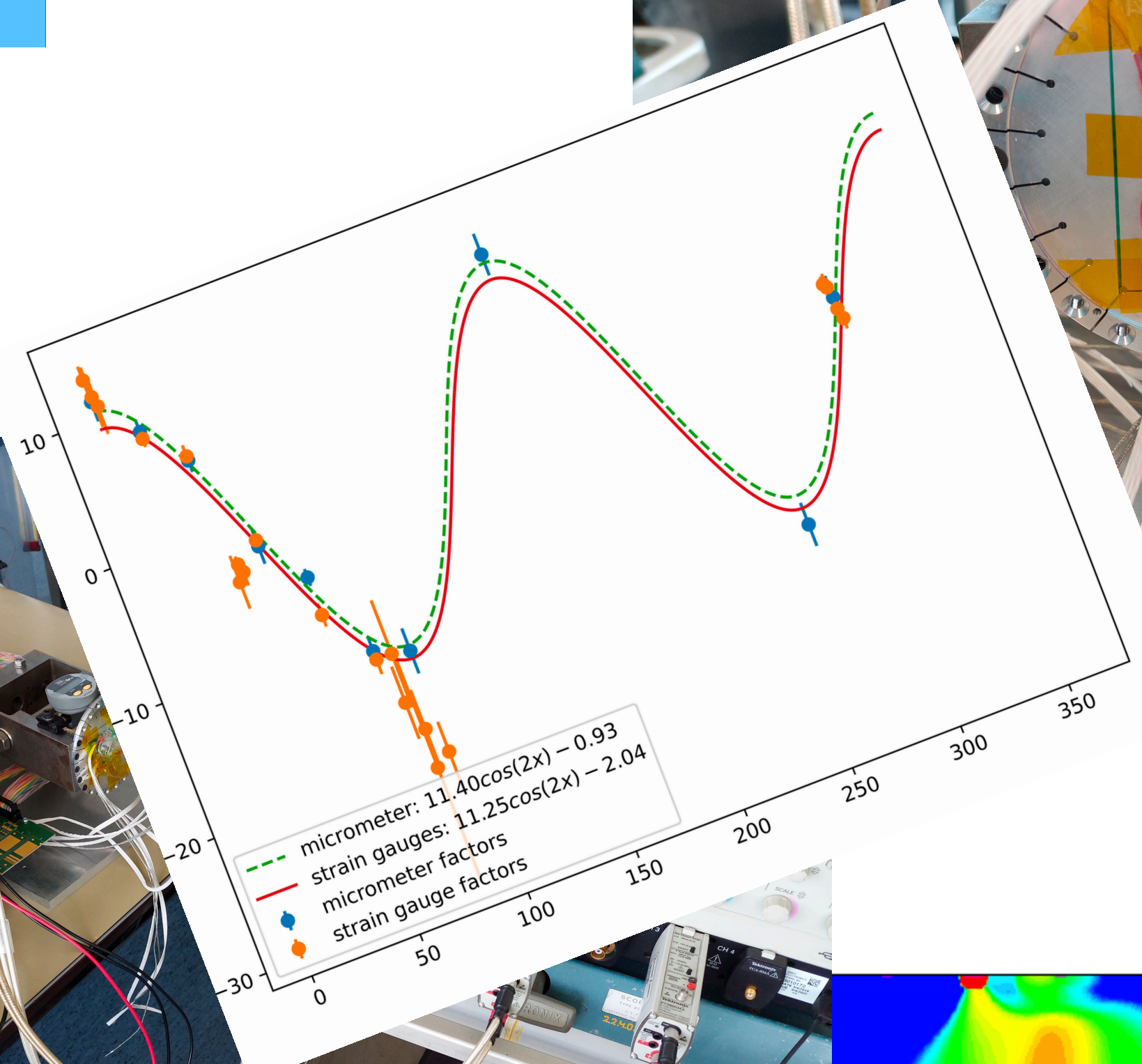
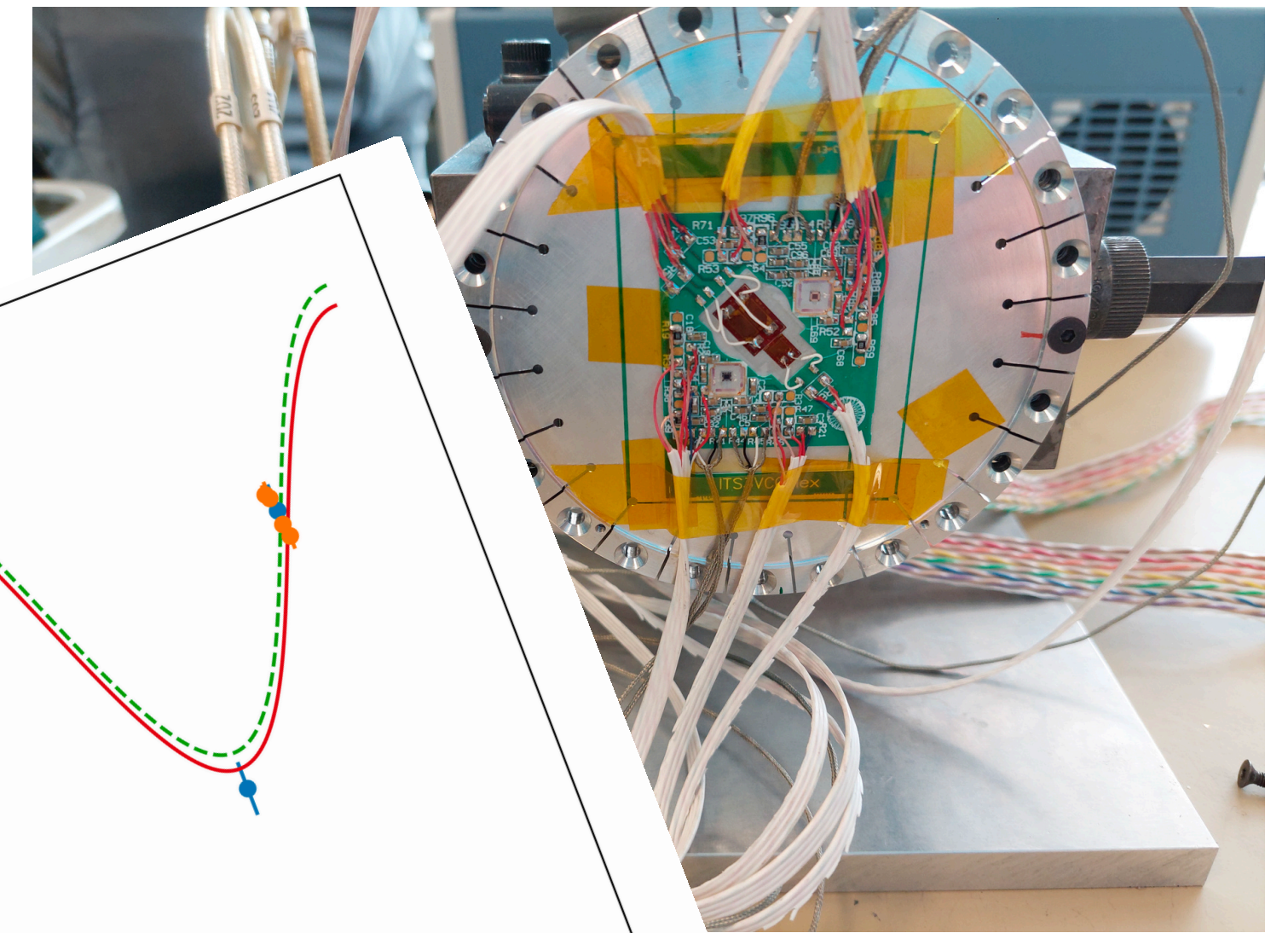
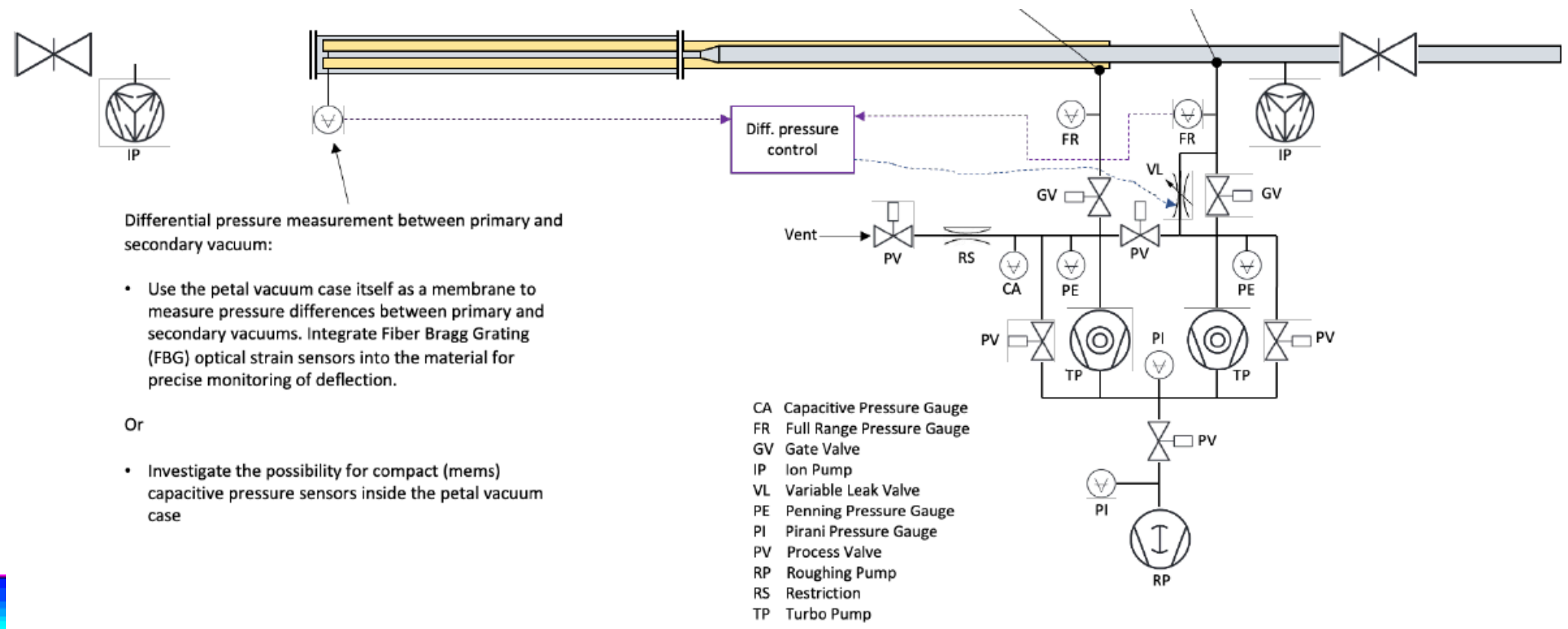
- ▶ Qualify for yield
- ▶ Measure time resolution

☑ Work on progress! Stay tuned

Pulsing the pixels



Much more ongoing but time is up



THANKS

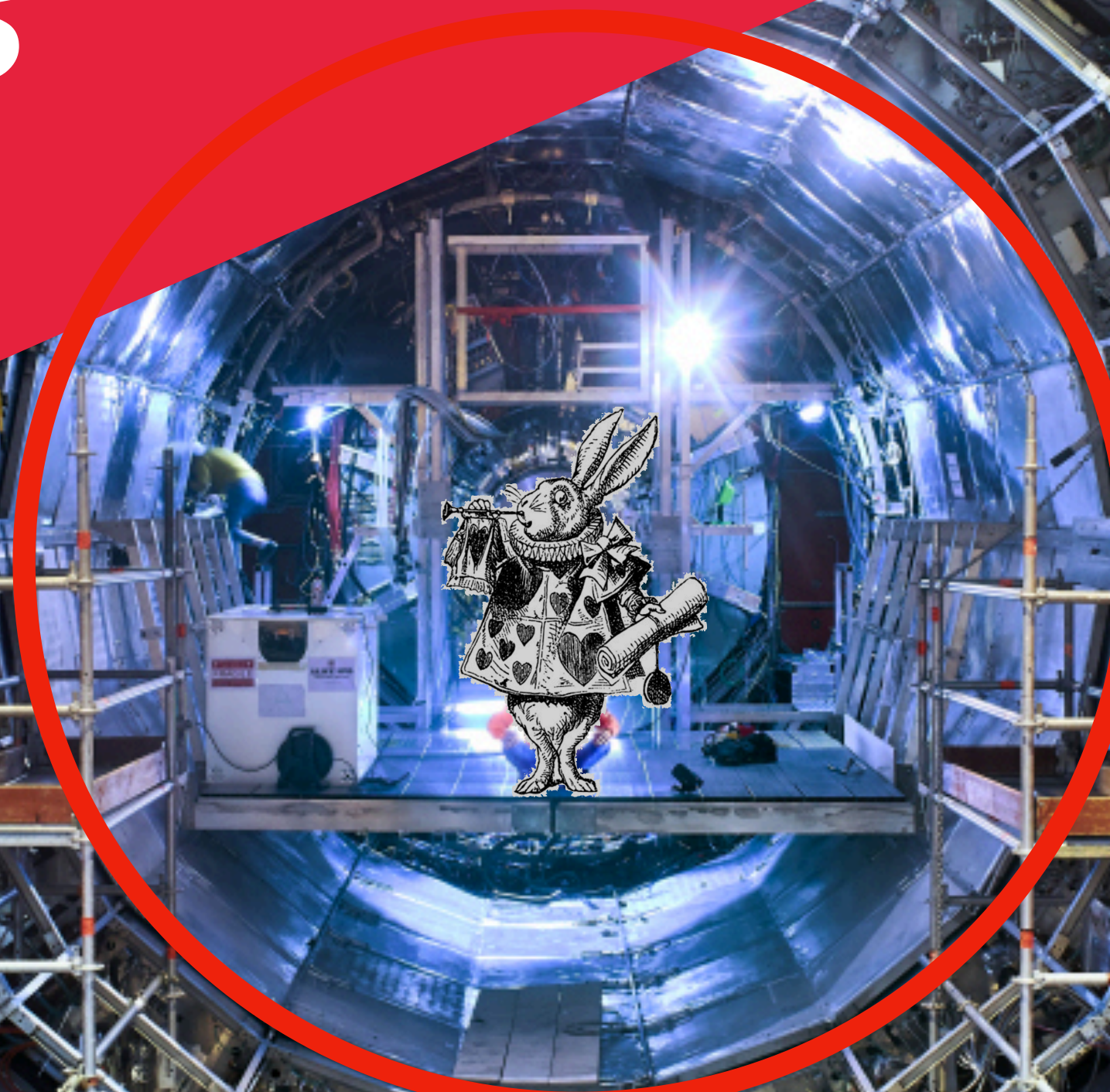


ALICE

Extra Slides

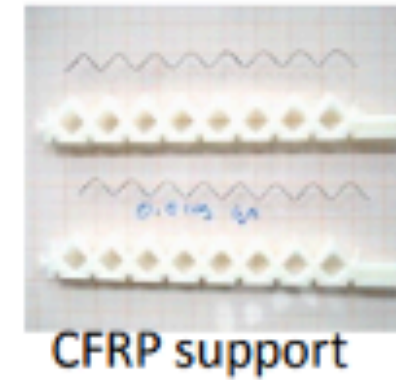
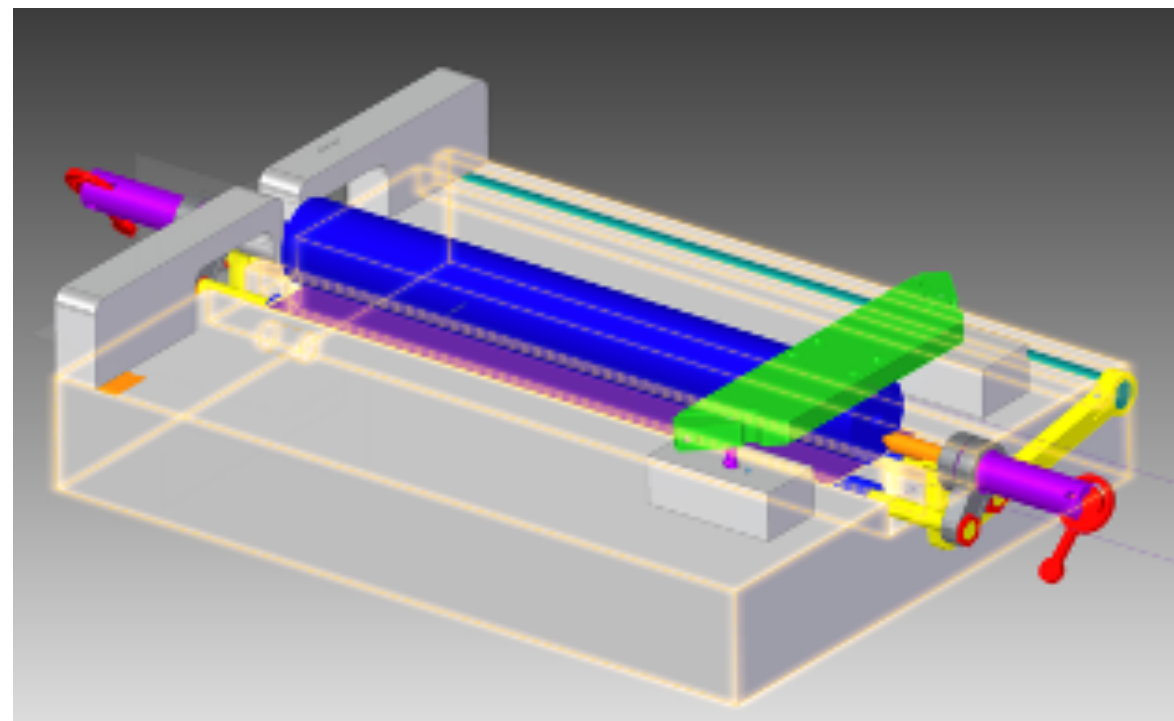
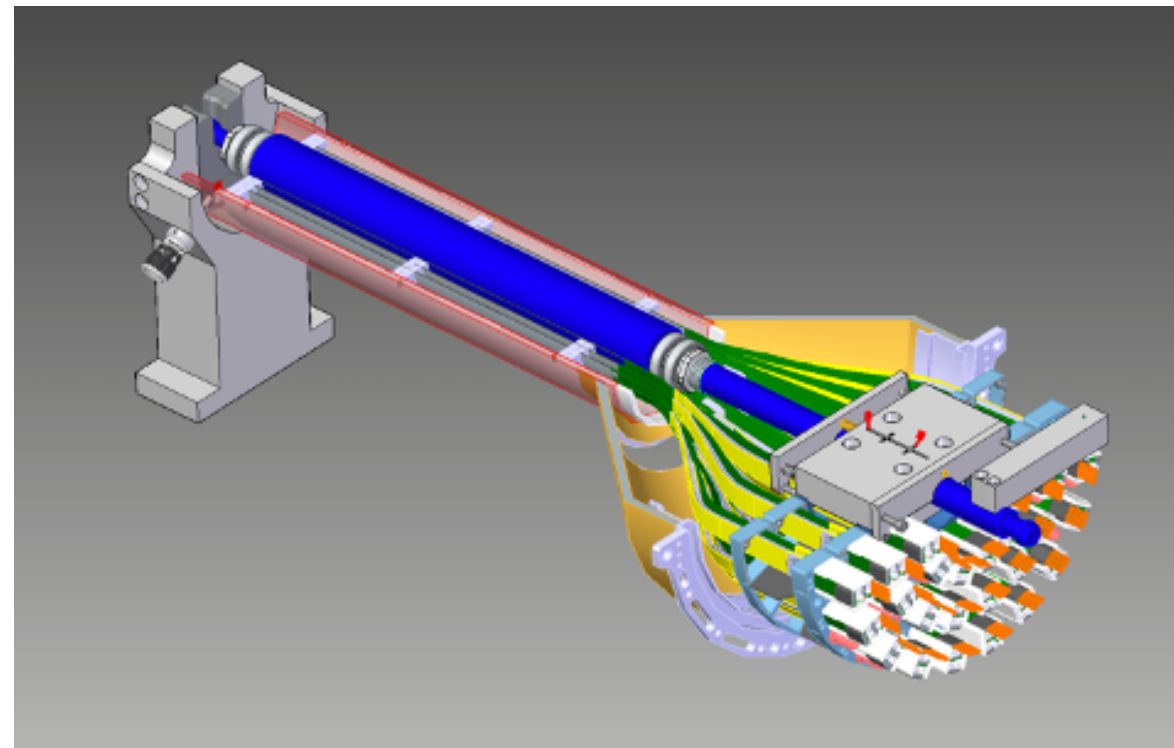
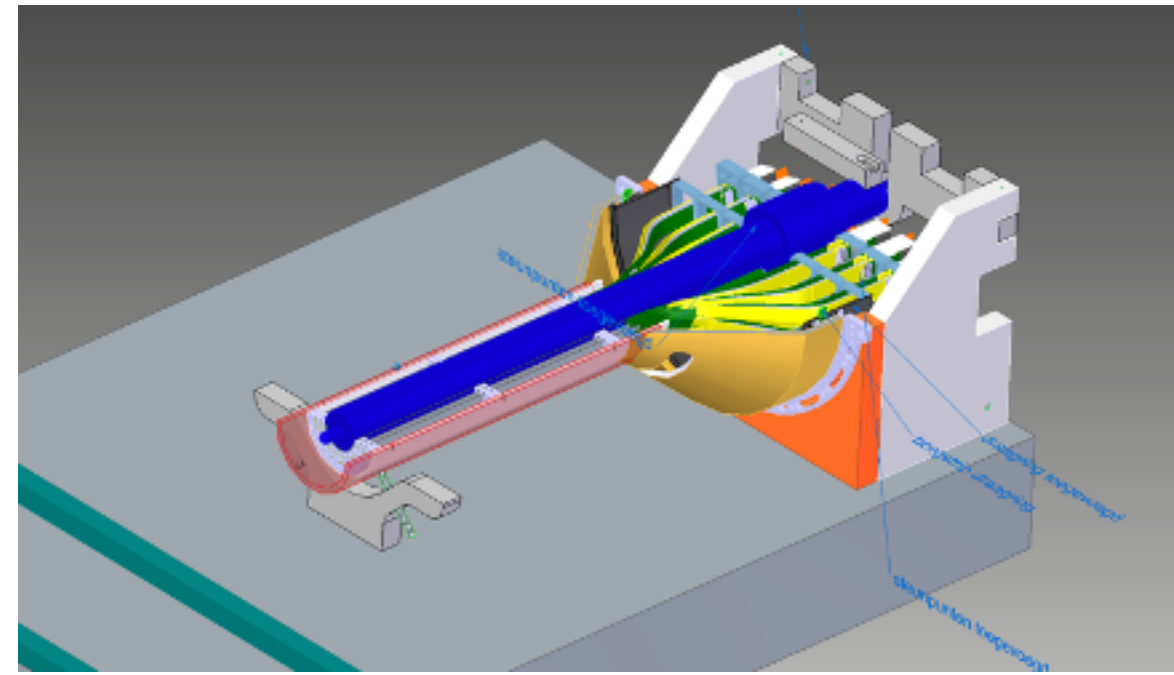


ALICE

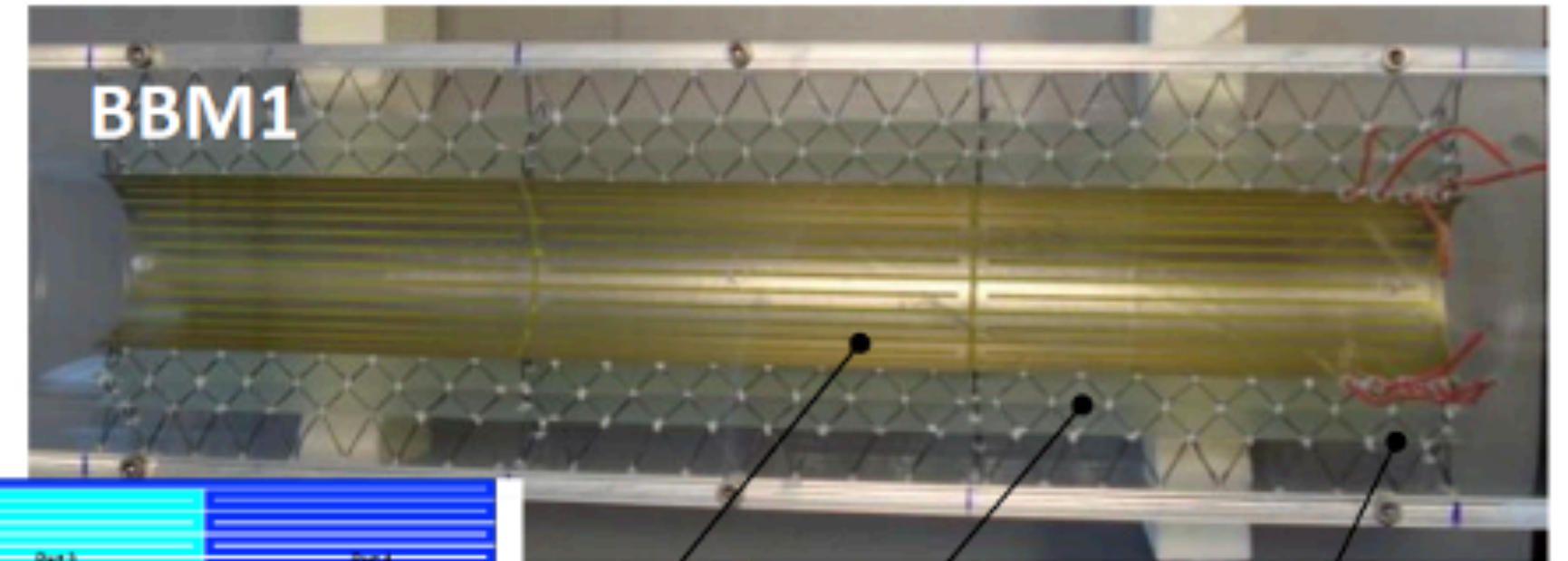


Nik|hef

Mechanics: Wind tunnel and assembly



CFRP support



Part of heater	Trace width, mm	Trace pitch, mm	Area, sq. mm	Voltage, V	Power, W/sq. cm
Part 1	-0.17	-0.31	-1.1	-4	-1.5
Part 2	-2.4	-3.6	-43	-6.3	-0.5
Part 3	-2.4	-3.6	-52	-6.7	-0.5
Part 4	-2.4	-3.6	-87	-9.8	-0.5

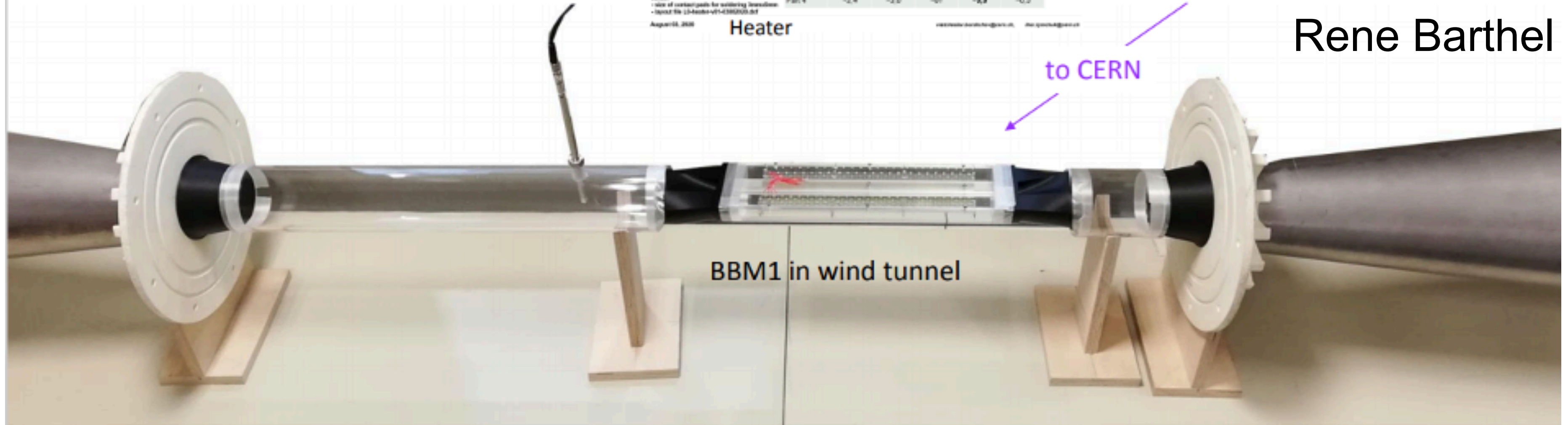
Heater

L0 L1 L2

from Nikhef

Rene Barthel

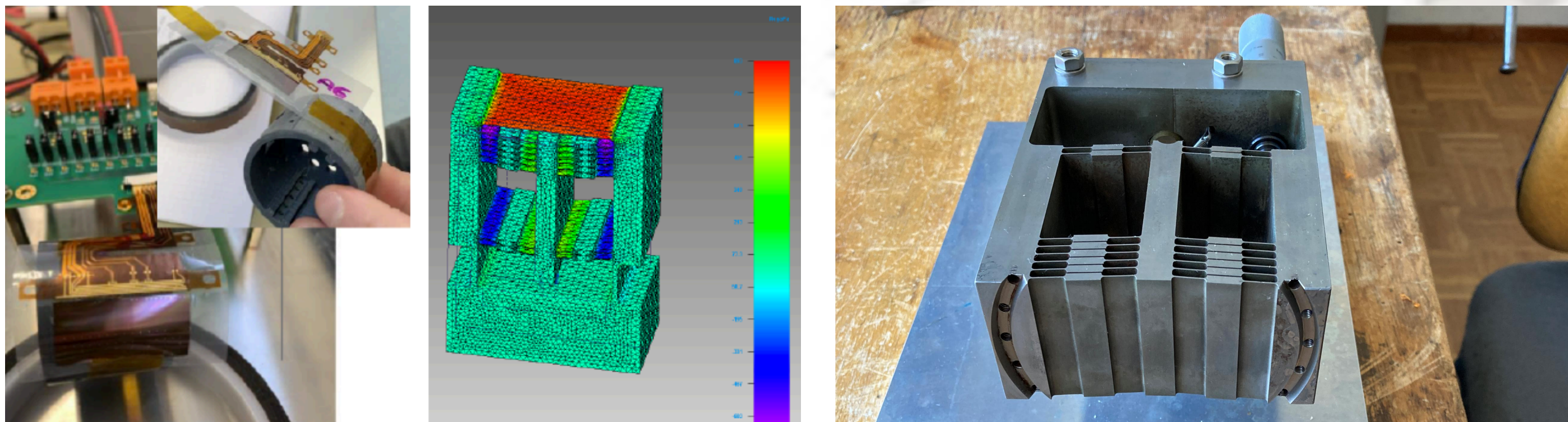
to CERN



BBM1 in wind tunnel

☑ Quite some nice activity in the last two years for what concerns mechanics, chip design and electronic

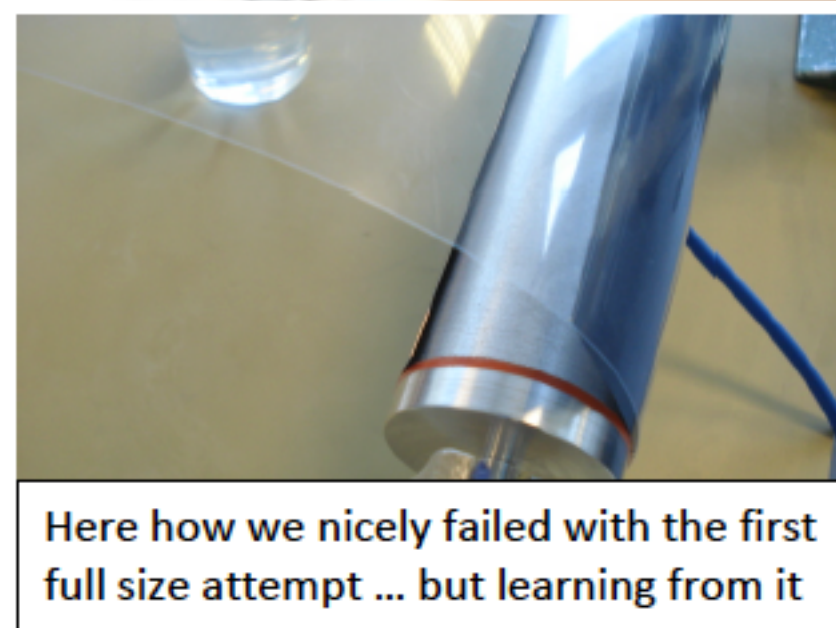
Piezoresistive effect: stretching and bending



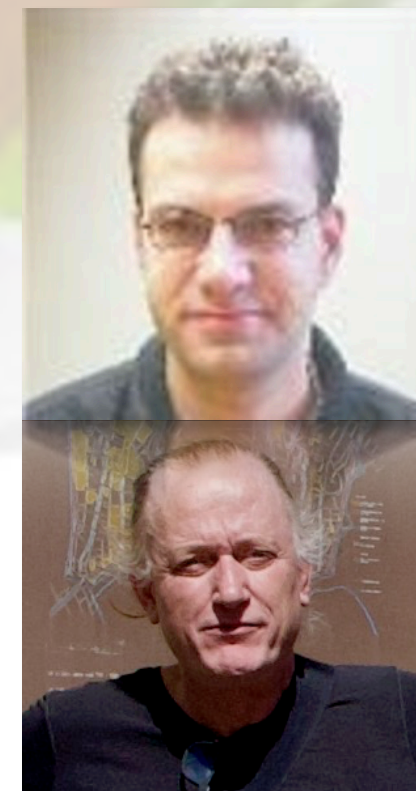
Tooling: Assembly tools



Here our nice full size porous aluminium vacuum grabbing tool



Here how we nicely failed with the first full size attempt ... but learning from it



Mechanics: wind tunnel studies

A summary of 2021 wind tunnel studies

CERN

Nikhef/Utrecht

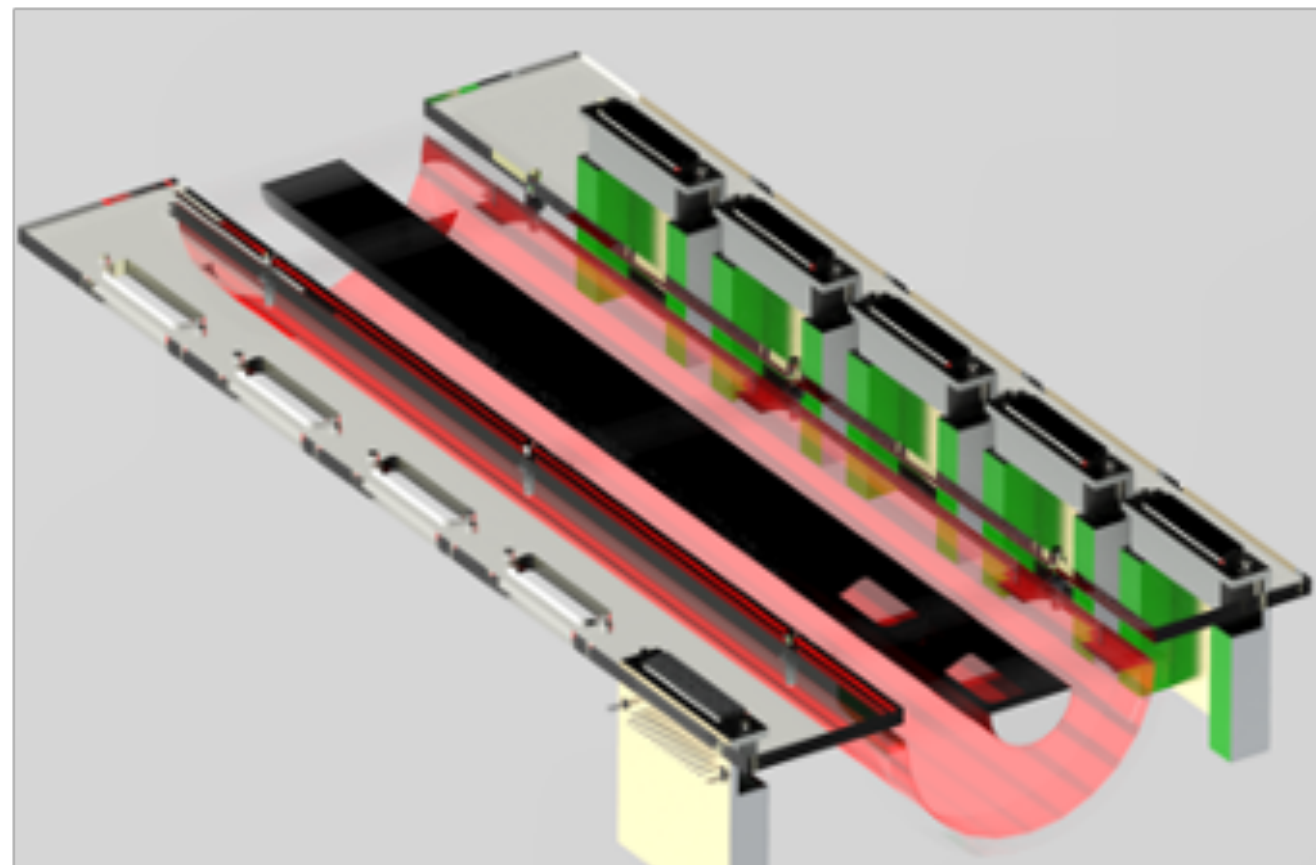
The image displays a detailed view of the experimental setup. On the right, several electronic modules are stacked, including what appears to be a signal conditioner and an oscilloscope. A dense network of cables connects these modules to the sensor assembly. The sensor assembly itself is a green PCB populated with various components, mounted on a blue support structure. The entire setup is situated in a laboratory environment with a large industrial fan or turbine in the background.

Below the main photograph, there are several smaller plots and graphs. These include:

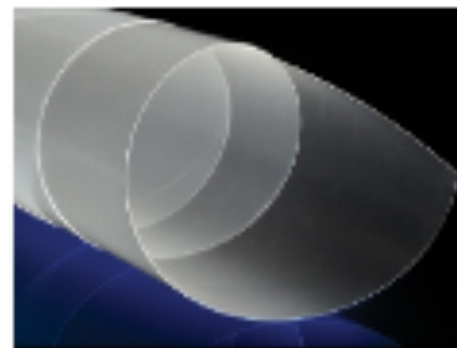
- A plot showing drift [mV] versus V_average [mV] for different sensor types (L3-F, L3-P).
- Another plot showing drift [mV] versus V_average [mV] for different sensor types (L3-F, L3-P).
- A plot showing drift [mV] versus V_average [mV] for different sensor types (L3-F, L3-P).
- A plot showing drift [mV] versus V_average [mV] for different sensor types (L3-F, L3-P).

Mechanics: Wind tunnel, what next

Preparations for BBM2



Infrared (IR) Material Windows



- Excellent Optics for Infrared Detectors
- Minimal Absorption Loss from 8 - 14µm
- Easily Cut to Size

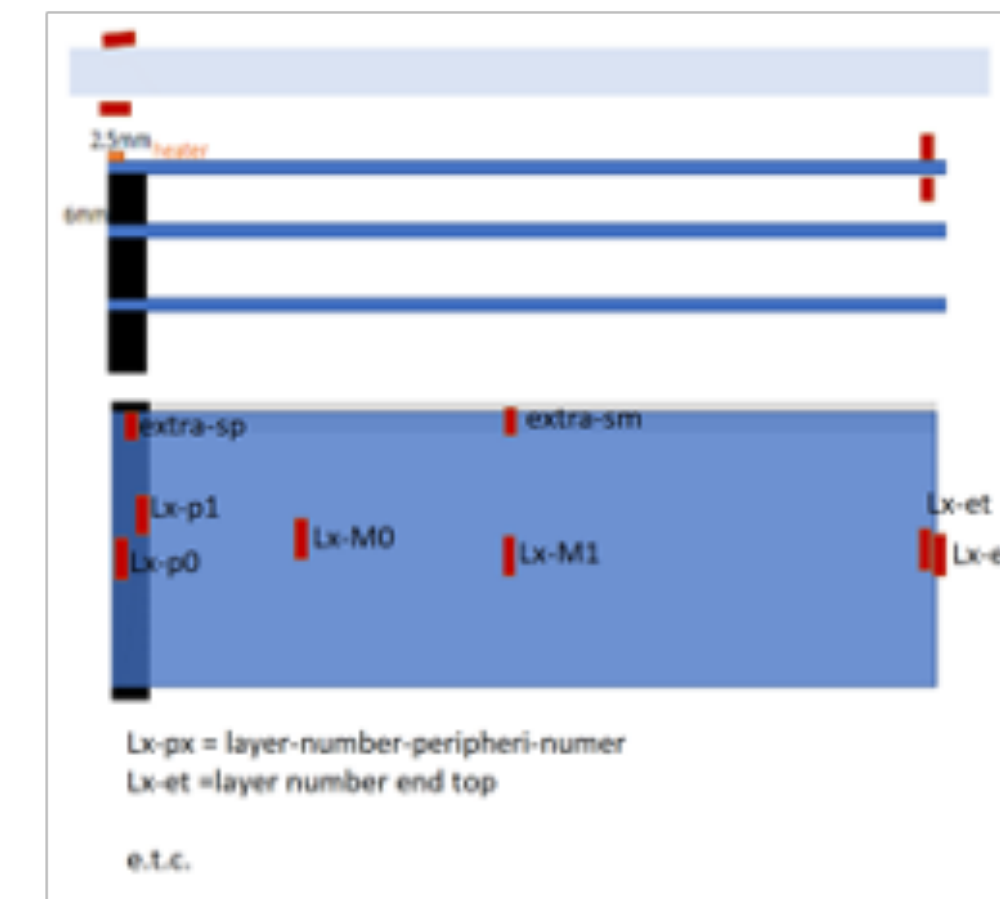
Common Specifications

Thickness (mm):	0.38	Thickness (Inches):	0.015
Coating:	Uncoated	Coefficient of Thermal Expansion CTE (10 ⁻⁶ /°C):	11 - 13
Flexural Modulus (psi):	(100-250) x 10 ³	Index of Refraction n _D :	Visible (Sodium D Line): 1.52 8-14µm: 1.53 15µm+: 1.48
Operating Temperature (°C):	100 (Max.)	Shore Hardness:	D60-70
Substrate:	Polymer Film	Wavelength Range (nm):	8000 - 14000
Young's Modulus (GPa):	0.40 - 1.24		



Item	Part	Quantity	Material	Notes
1	IR-D-01	1	IR-D-01	
2	IR-D-02	1	IR-D-02	
3	IR-D-03	1	IR-D-03	
4	IR-D-04	1	IR-D-04	
5	IR-D-05	1	IR-D-05	
6	IR-D-06	1	IR-D-06	
7	IR-D-07	1	IR-D-07	
8	IR-D-08	1	IR-D-08	
9	IR-D-09	1	IR-D-09	
10	IR-D-10	1	IR-D-10	
11	IR-D-11	1	IR-D-11	
12	IR-D-12	1	IR-D-12	
13	IR-D-13	1	IR-D-13	
14	IR-D-14	1	IR-D-14	
15	IR-D-15	1	IR-D-15	
16	IR-D-16	1	IR-D-16	
17	IR-D-17	1	IR-D-17	
18	IR-D-18	1	IR-D-18	
19	IR-D-19	1	IR-D-19	
20	IR-D-20	1	IR-D-20	
21	IR-D-21	1	IR-D-21	
22	IR-D-22	1	IR-D-22	
23	IR-D-23	1	IR-D-23	
24	IR-D-24	1	IR-D-24	
25	IR-D-25	1	IR-D-25	

Will provide list with connections



Rene Barthel



A selection of ALICE hardware activities

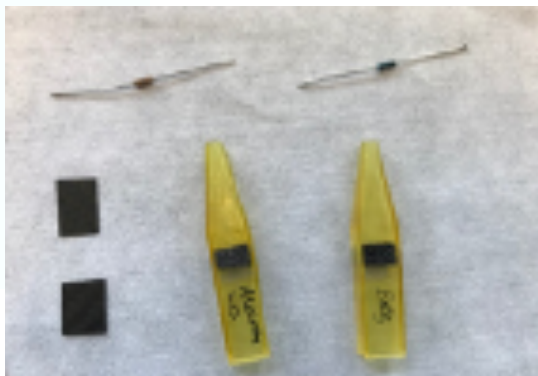
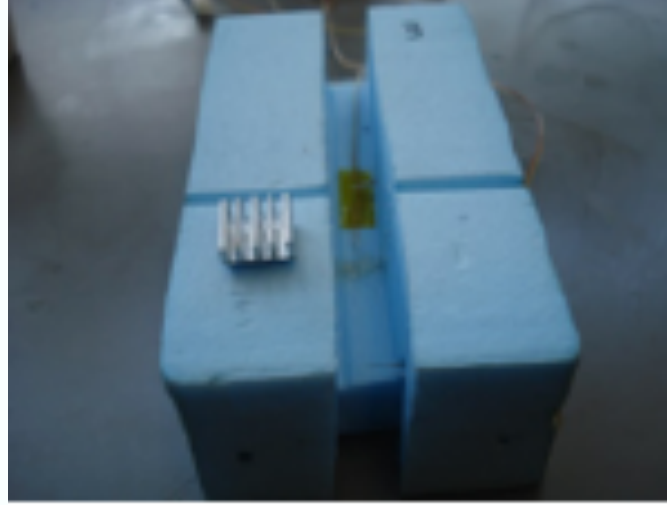
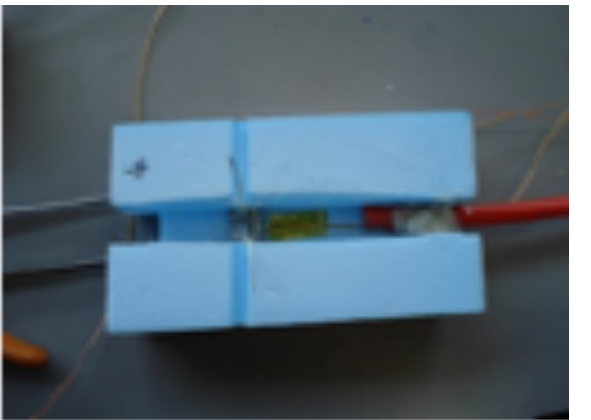
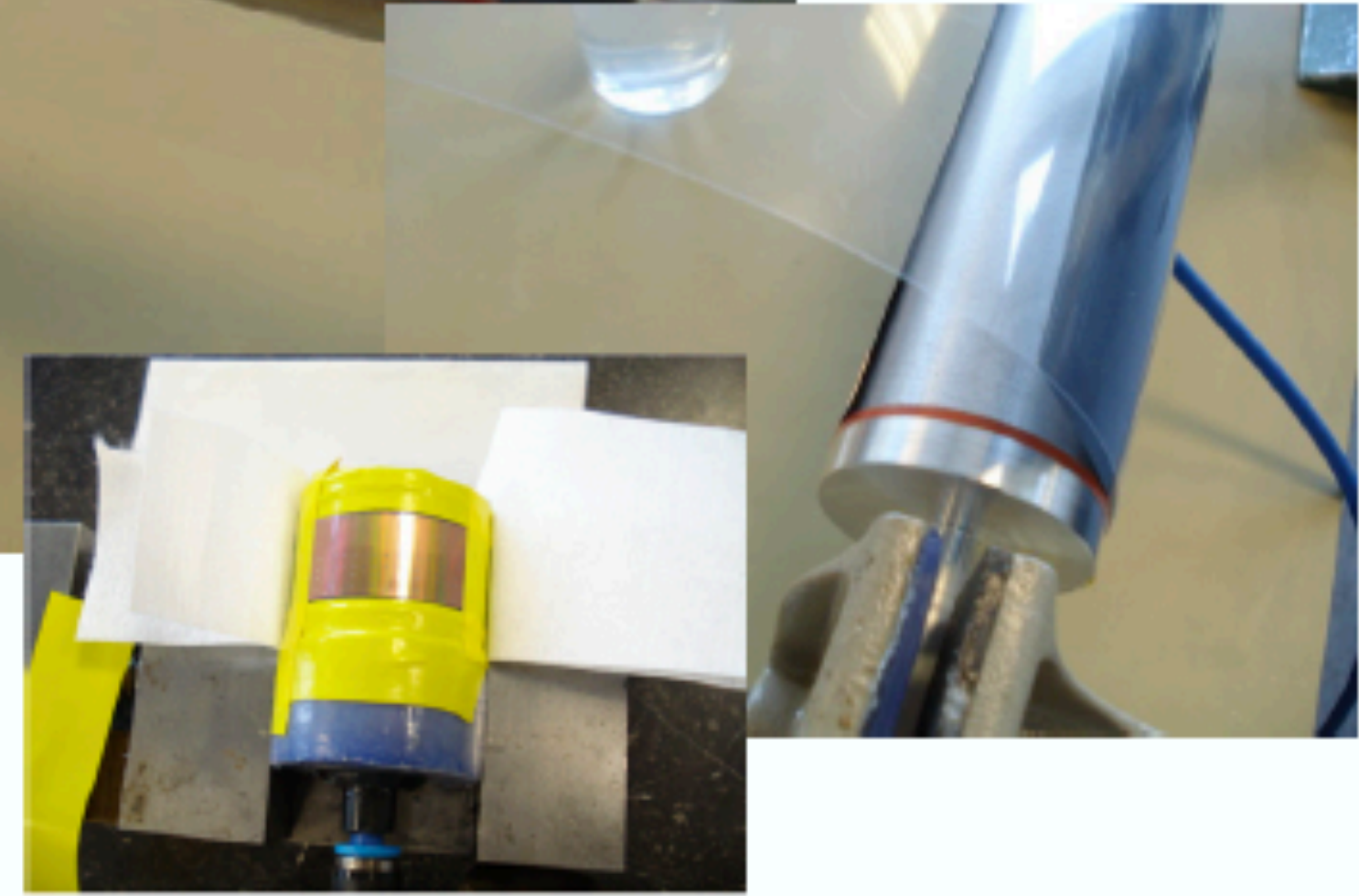
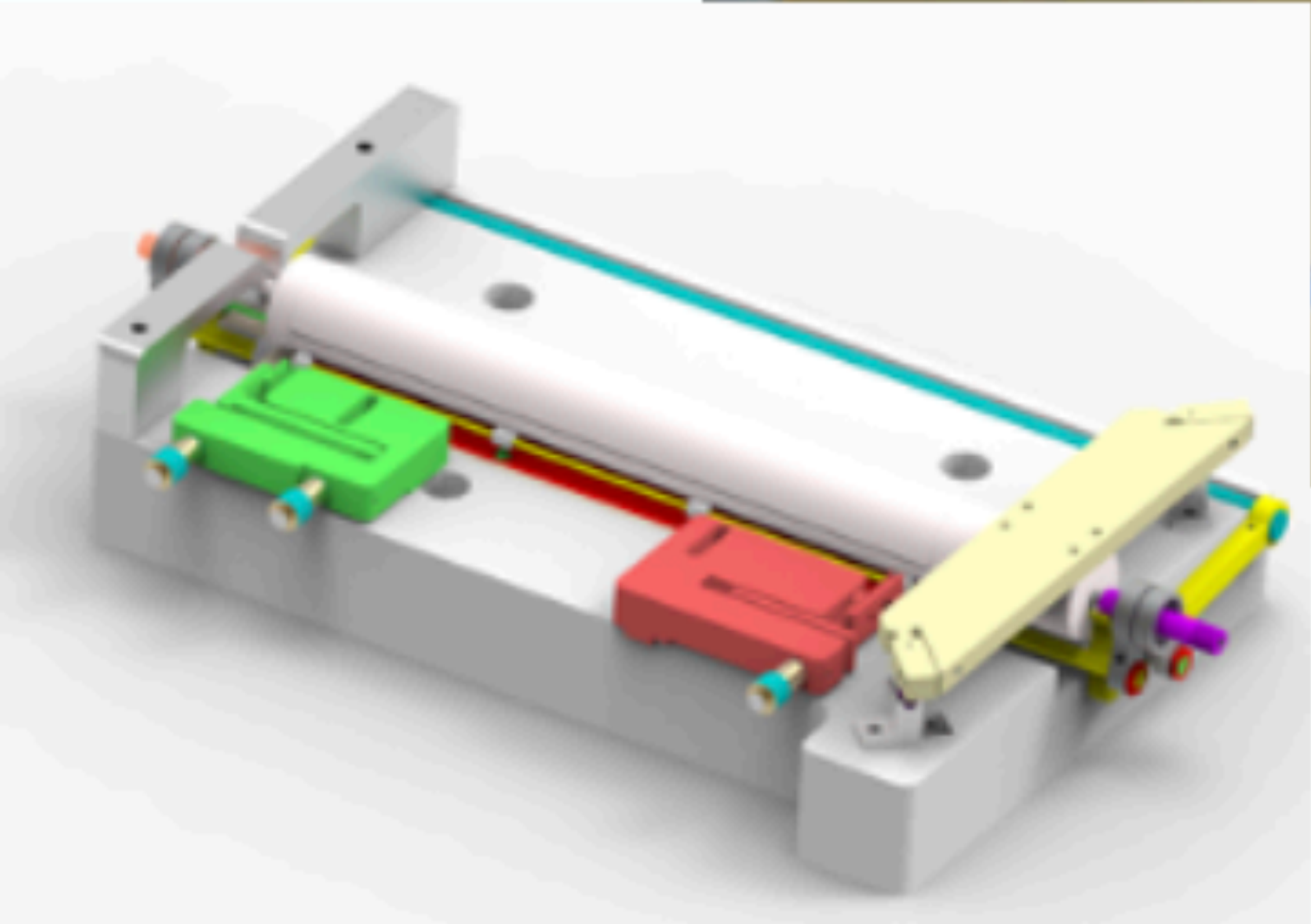


Mechanics: Vacuum bending tools and carbon foam

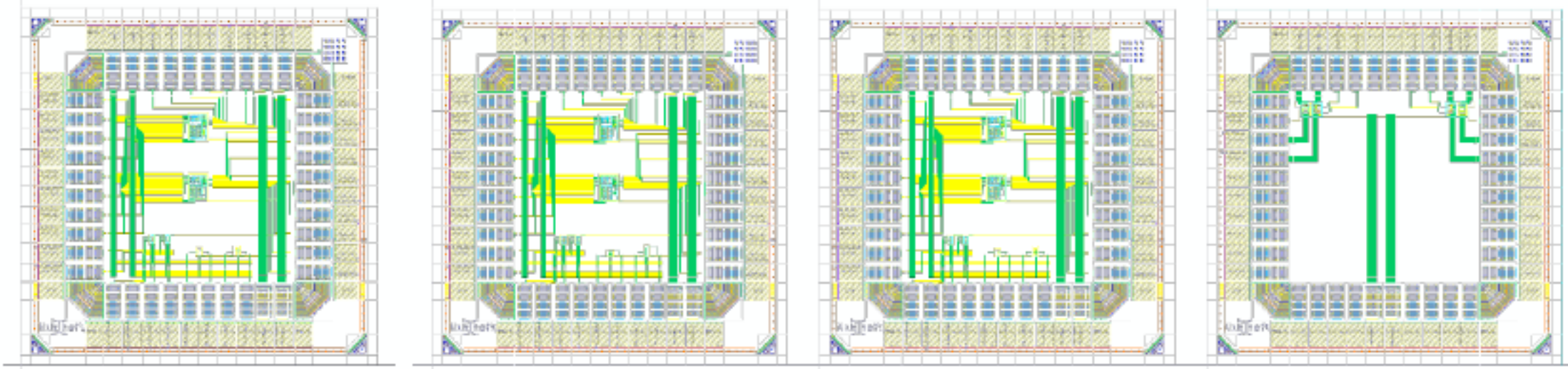
Rene Barthel



If work this will be Really a major success



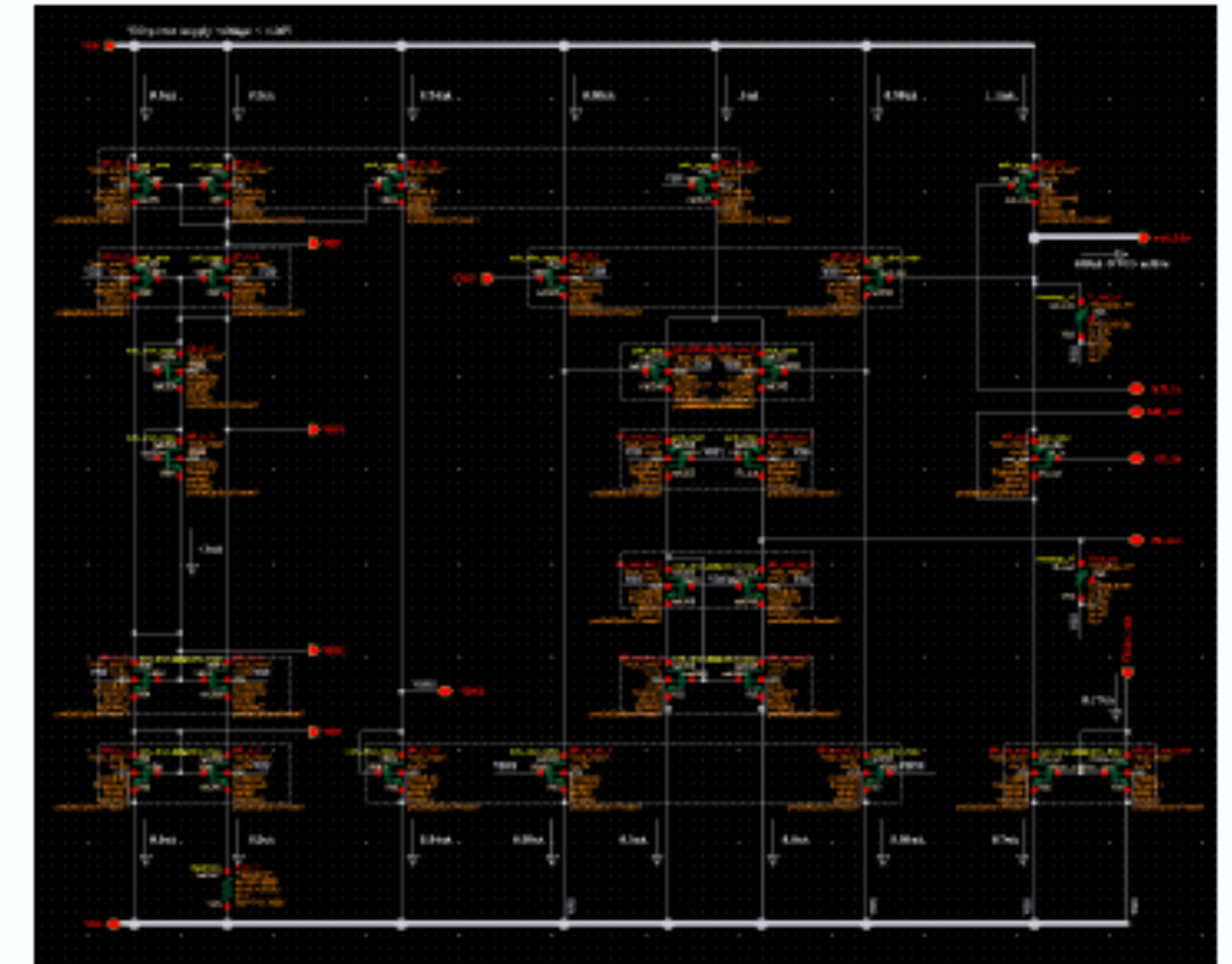
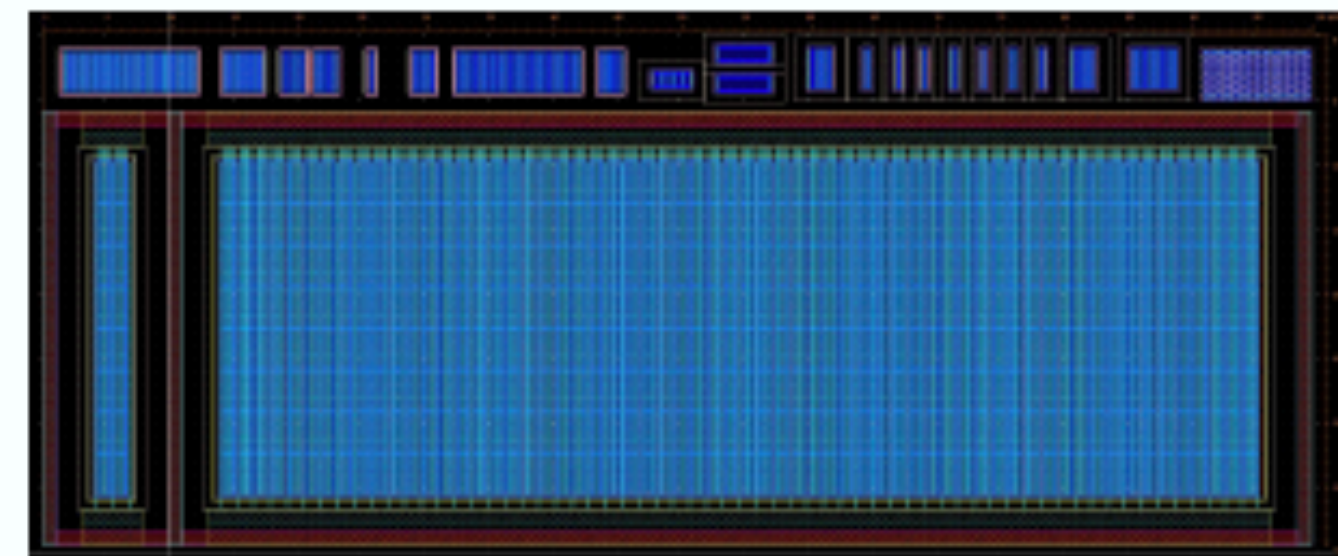
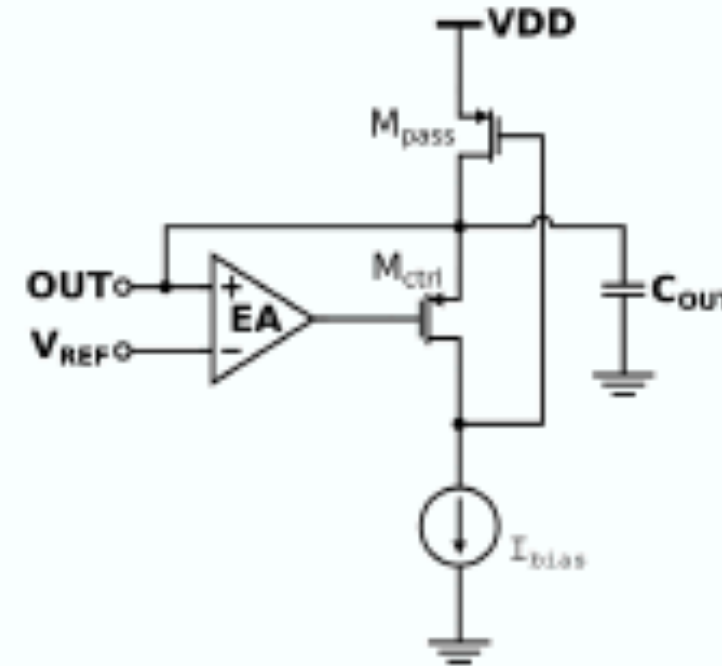
Design: Band Gaps (x4), VCO, Tsensor, LDO and PLL



- GDS, along with DRC, ESD and LVS summary of four dies delivered to CERN.
- Die I – Diode and PNP BGR circuits.
- Die II – DTMOS and diode gated BGR circuits.
- Die III – Diode and PNP TS circuits.
- Die IV – pch IMOST varactor and nch IMOST varactor VCOs.

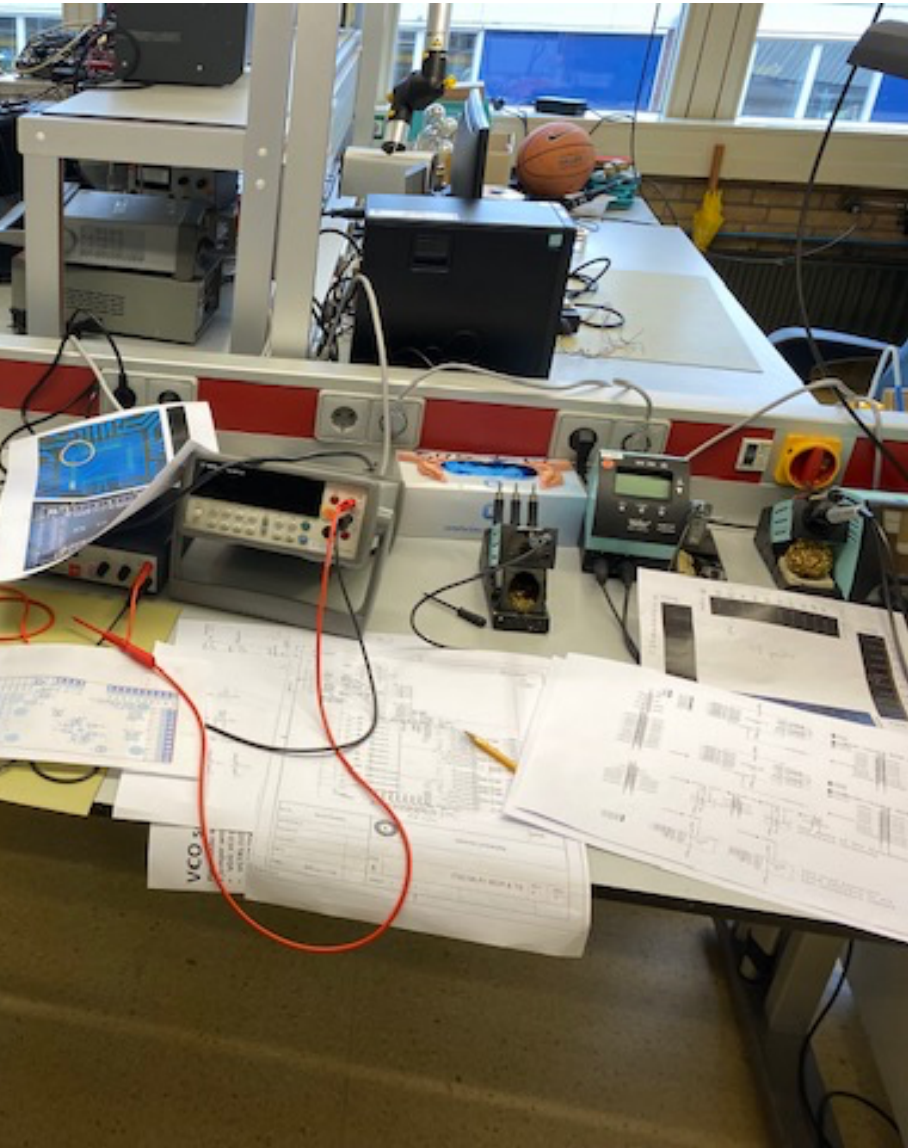
LDO

- ✓ LDO and PLL already designed. Still a month of checks needed but we will be ready by the end of November 2021 (perfectly in time)



Deepak, Vladimir, Asli

Test of designed structures

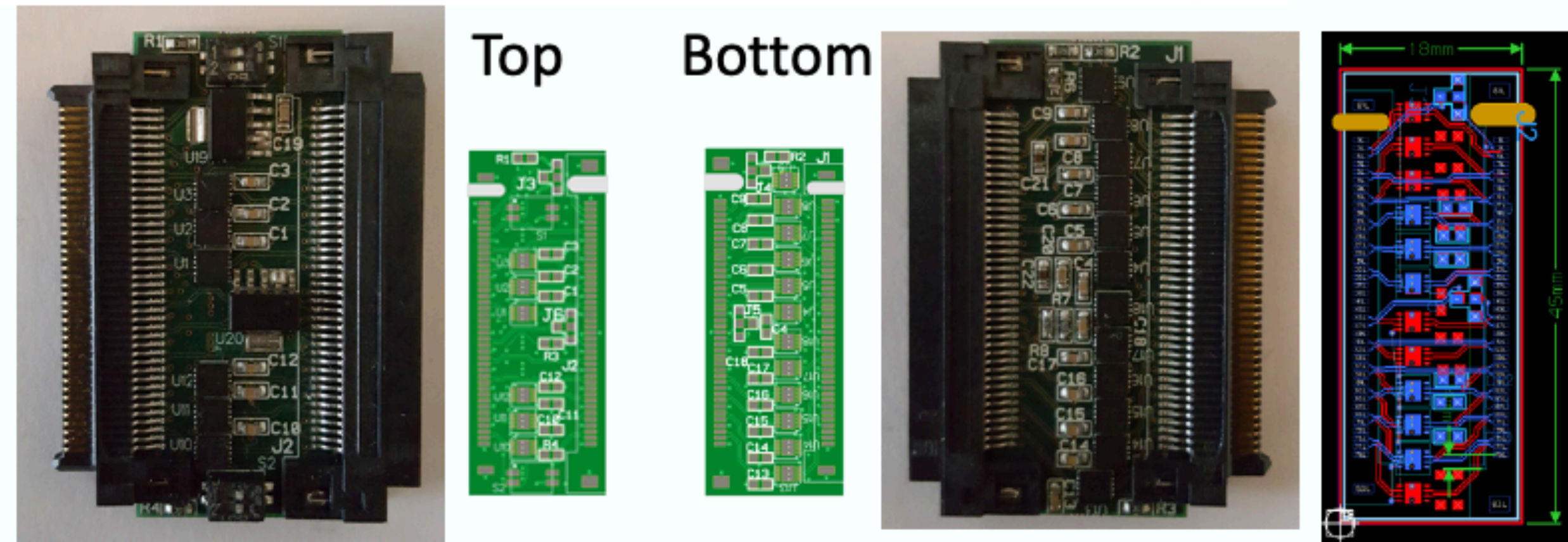
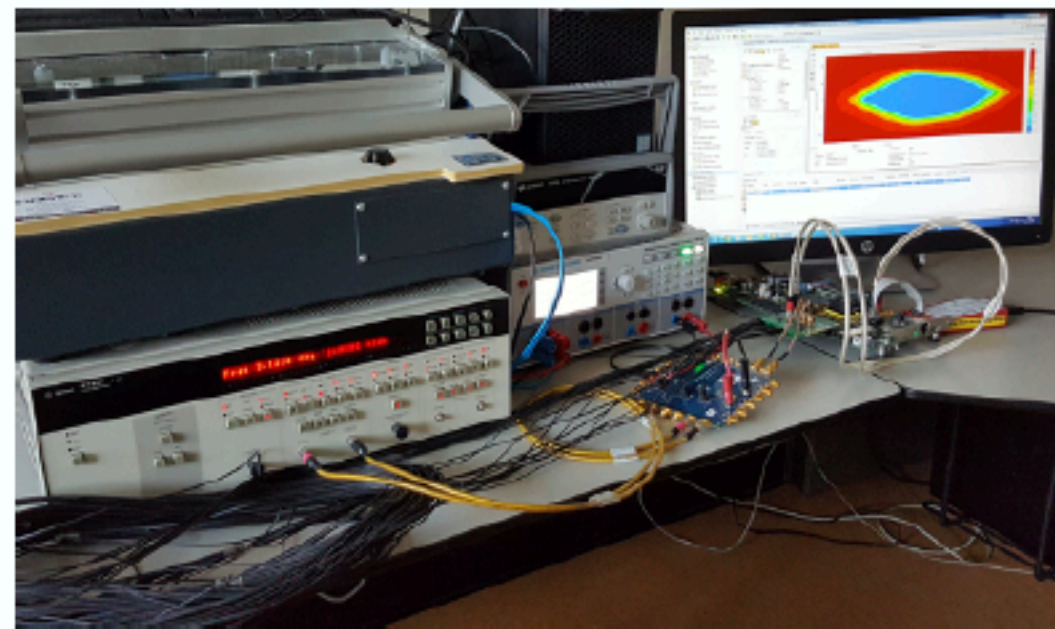
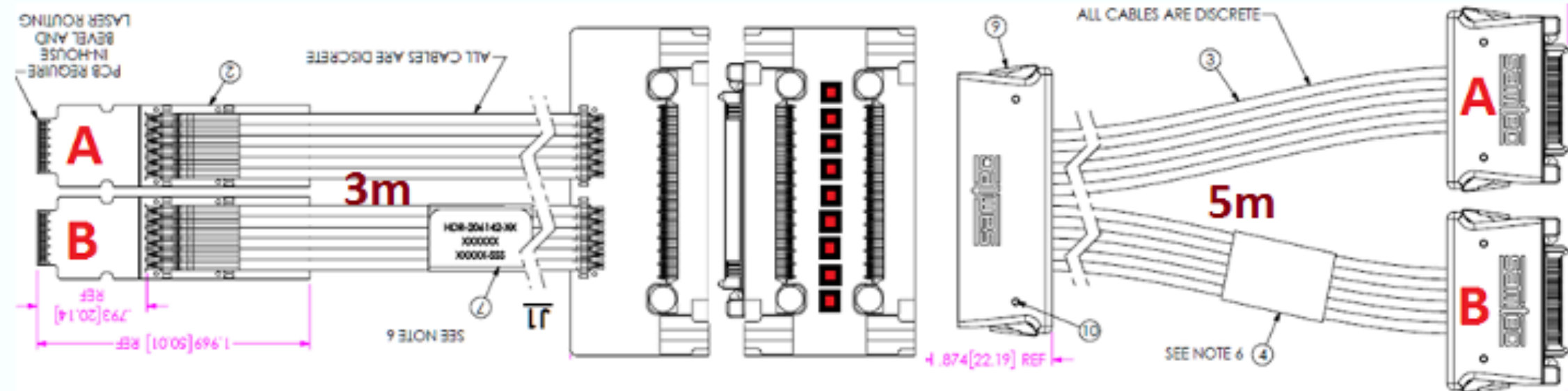


Marcel Rosswji, Shi, Vladimir + MT bonding lab

Fast Link: Cable studies and intermediate board

Rate Mbps	Pre-emphasis DS25BR120	Cable length			
		0m	4m	8m	3+5m
2000	0		3.17		
	1		4.8	2.6	2.4
	10		6.8	3.4	3.1
2500	11		11.6	5.1	4.3
	0		3	1.6	1.6
	1		4.2	2.2	1.9
3000	10		5.6	2.5	2.3
	11		8.1	3.7	3
	0	12.4	2.2	1.6	-
3000	1	6.9	3.4	1.7	-
	10	5.2	4.4	1.9	-
	11	4.8	6.6	2.5	-

Check if buffer between 3+5m cable improves rate

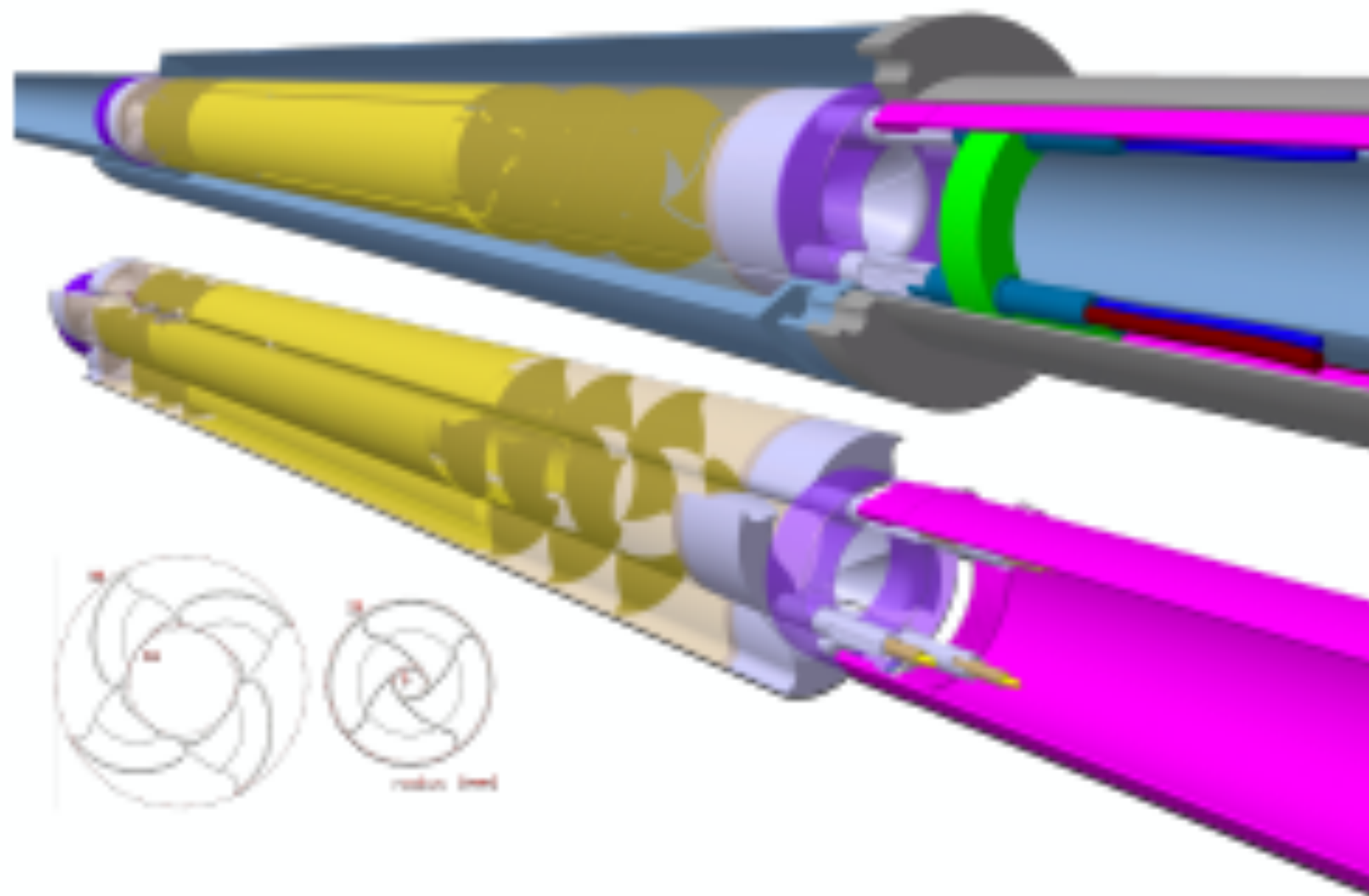


Marcel Rossewji, (and Vladimir in 2020)

ALICE3 tracker concept

Vertex detector

A marvel of technology



Tracker

A big, improved ITS2

